

Advanced LinCMOS™ RAIL-TO-RAIL OUTPUT WIDE-INPUT-VOLTAGE OPERATIONAL AMPLIFIERS

FEATURES

- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Output Swing Includes Both Supply Rails
- Extended Common-Mode Input Voltage Range: 0 V to 4.25 V (Min) at 5-V Single Supply
- No Phase Inversion
- Low Noise: 16 nV/√Hz Typ at f = 1 kHz
- Low Input Offset Voltage: 950 μV Max at T_A = 25°C (TLV244xA)
- Low Input Bias Current: 1 pA (Typ)
- 600-Ω Output Drive
- High-Gain Bandwidth: 1.8 MHz (Typ)
- Low Supply Current: 750 μA Per Channel (Typ)
- Macromodel Included

DESCRIPTION

The TLV244x and TLV244xA are low-voltage operational amplifiers from Texas Instruments. The common-mode input voltage range of these devices has been extended over typical standard CMOS amplifiers, making them suitable for a wide range of applications. In addition, these devices do not phase invert when the common-mode input is driven to the supply rails. This satisfies most design requirements without paying a premium for rail-to-rail input performance. They also exhibit rail-to-rail output performance for increased dynamic range in single- or split-supply applications. This family is fully characterized at 3-V and 5-V supplies and is optimized for low-voltage operation. Both devices offer comparable ac performance while having lower noise, input offset voltage, and power dissipation than existing CMOS operational amplifiers. The TLV244x has increased output drive over previous rail-to-rail operational amplifiers and can drive 600-Ω loads for telecommunications applications.

The other members in the TLV244x family are the low-power, TLV243x, and micro-power, TLV2422, versions.

The TLV244x, exhibiting high input impedance and low noise, is excellent for small-signal conditioning for high-impedance sources, such as piezoelectric transducers. Because of the micropower dissipation levels and low-voltage operation, these devices work well in hand-held monitoring and remote-sensing applications. In addition, the rail-to-rail output feature with single- or split-supplies makes this family a great choice when interfacing with analog-to-digital converters (ADCs). For precision applications, the TLV244xA is available with a maximum input offset voltage of 950 μV.

If the design requires single operational amplifiers, see the TI TLV2211/21/31. This is a family of rail-to-rail output operational amplifiers in the SOT-23 package. Their small size and low power consumption make them ideal for high-density battery-powered equipment.

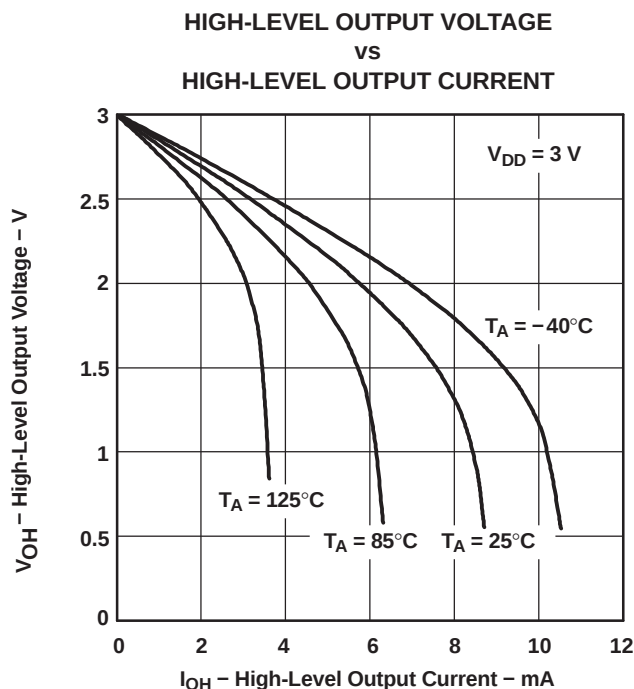


Figure 1.



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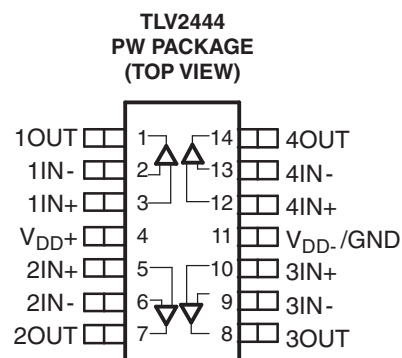
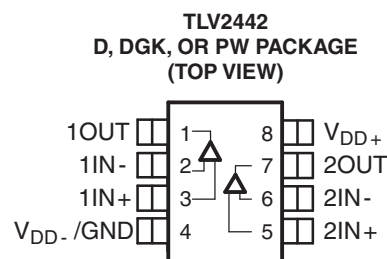
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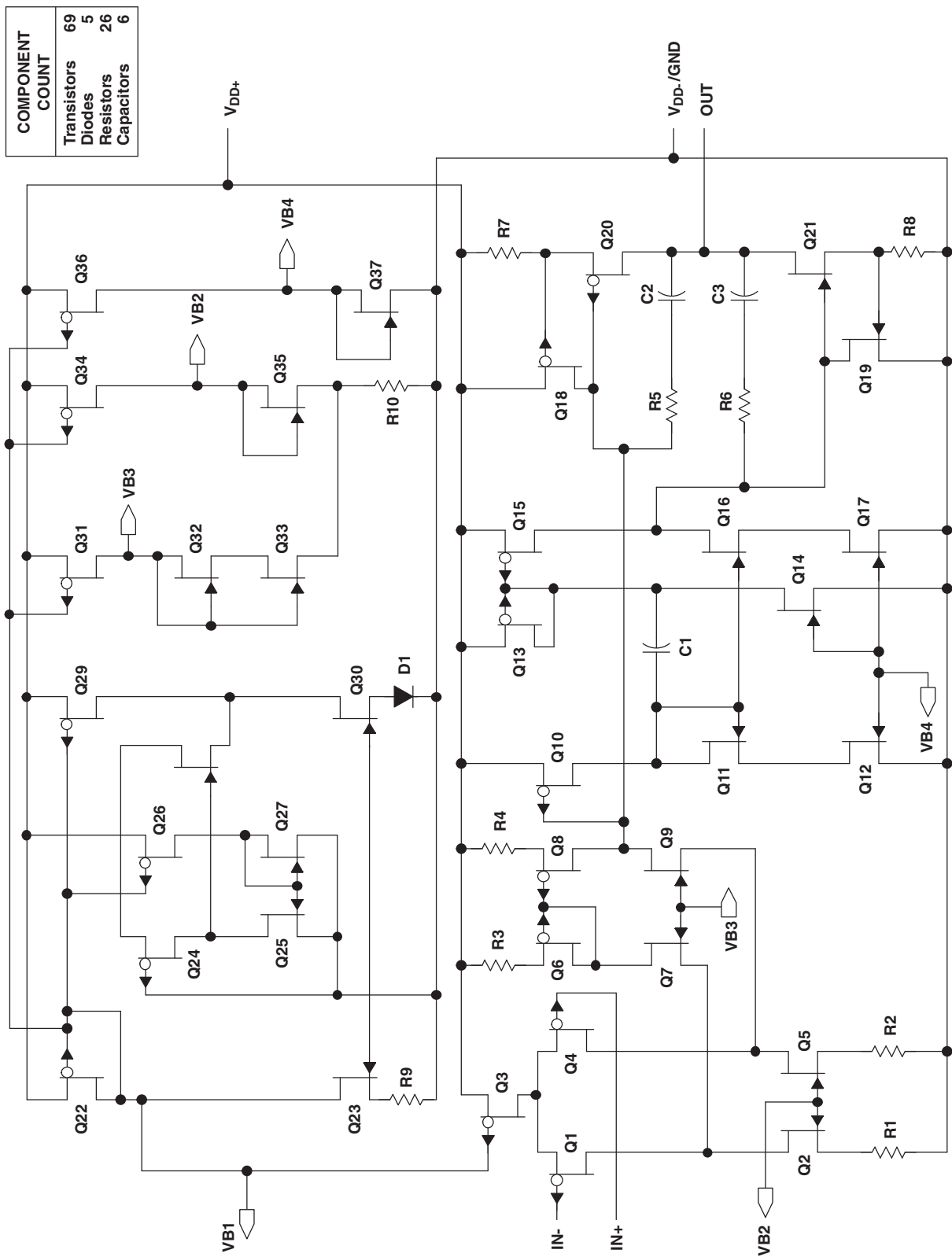
ORDERING INFORMATION⁽¹⁾

T_A	$V_{IO\max}$ AT 25°C	PACKAGE ⁽²⁾			ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	950 μ V	Dual	SOIC – D	Reel of 2500	TLV2442AQDRQ1	2442AQ
			TSSOP – PW	Reel of 2000	TLV2442AQPWRQ1	2442AQ
	2.5 mV	Dual	MSOP – DGK	Reel of 2500	TLV2442QDGKRQ1	OBR
			SOIC – D	Reel of 2500	TLV2442QDRQ1	2442Q1
			TSSOP – PW	Reel of 2000	TLV2442QPWRQ1	2442Q1
	950 μ V	Quad	TSSOP – PW	Reel of 2000	TLV2444AQPWRQ1	2444AQ

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



EQUIVALENT SCHEMATIC (EACH AMPLIFIER)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

V_{DD}	Supply voltage ⁽²⁾	12 V
V_{ID}	Differential input voltage ⁽³⁾	$\pm V_{DD}$
V_I	Input voltage (any input) ⁽²⁾	-0.3 V to V_{DD}
I_I	Input current (any input)	± 5 mA
I_O	Output current	± 50 mA
	Total current into V_{DD+}	± 50 mA
	Total current out of V_{DD-}	± 50 mA
	Duration of short-circuit current at (or below) 25°C ⁽⁴⁾	Unlimited
	Continuous total dissipation	See Dissipation Rating Table
T_A	Operating free-air temperature range	-40°C to 125°C
T_{stg}	Storage temperature range	-65°C to 150°C
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the midpoint between V_{DD+} and V_{DD-} .
- (3) Differential voltages are at $IN+$ with respect to $IN-$. Excessive current will flow if input is brought below $V_{DD-} - 0.3$ V.
- (4) The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION RATINGS

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D (8 pin)	725 mW	5.8 mW/ $^\circ\text{C}$	464 mW	377 mW	145 mW
DGK (8 pin)	606 mW	4.847 mW/ $^\circ\text{C}$	388 mW	315 mW	121 mW
PW (8 pin)	525 mW	4.2 mW/ $^\circ\text{C}$	336 mW	273 mW	105 mW
PW (14 pin)	720 mW	5.6 mW/ $^\circ\text{C}$	634 mW	547 mW	317 mW

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V_{DD}	Supply voltage	2.7	10	V
V_I	Input voltage	V_{DD-}	$V_{DD+} - 1$	V
V_{IC}	Common-mode input voltage	V_{DD-}	$V_{DD+} - 1$	V
T_A	Operating free-air temperature	-40	125	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS

 $V_{DD} = 3\text{ V}$, at specified free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A ⁽¹⁾	MIN	TYP	MAX	UNIT
V _{IO}	Input offset voltage	V _{IC} = 1.5 V, V _O = 1.5 V, R _S = 50 Ω	TLV244x	25°C		300	2000	μV
				Full range		2500		
			TLV244xA	25°C		300	950	
				Full range		1600		
α _{VIO}	Temperature coefficient of input offset voltage	V _{IC} = 1.5 V, V _O = 1.5 V, R _S = 50 Ω		25°C to 85°C		2		μV/°C
	Input offset voltage long-term drift ⁽²⁾	V _{IC} = 1.5 V, V _O = 1.5 V, R _S = 50 Ω		25°C		0.002		μV/mo
I _{IO}	Input offset current	V _{IC} = 1.5 V, V _O = 1.5 V, R _S = 50 Ω		25°C		0.5		pA
				Full range		150		
I _{IB}	Input bias current	V _{IC} = 1.5 V, V _O = 1.5 V, R _S = 50 Ω		25°C		1		pA
				Full range		260		
V _{ICR}	Common-mode input voltage range	V _{IO} ≤ 8 mV, R _S = 50 Ω		25°C		0 to 2.25	−0.25 to 2.5	V
				Full range		0.2 to 2		
V _{OH}	High-level output voltage	I _O = −100 μA		25°C		2.98		V
		I _O = −3 mA		25°C		2.5		
				Full range		2.25		
V _{OL}	Low-level output voltage	V _{IC} = 1.5 V	I _O = 100 μA	25°C		0.02		V
			I _O = 3 mA	25°C		0.63		
				Full range		1		
A _{VD}	Large-signal differential voltage amplification	V _O = 1 V to 2 V	R _L = 600 Ω	25°C		0.7	1	V/mV
			R _L = 1 MΩ	Full range		0.4		
					25°C		750	
r _{id}	Differential input resistance			25°C		1000		GΩ
r _i	Common-mode input resistance			25°C		1000		GΩ
c _i	Common-mode input capacitance	f = 10 kHz		25°C		8		pF
z _o	Closed-loop output impedance	f = 1 MHz, A _V = 10		25°C		130		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICR} MIN, V _O = V _{DD} /2, R _S = 50 Ω		25°C		65	75	dB
				Full range		50		
k _{SVR}	Supply-voltage rejection ratio (ΔV _{DD} ±/ΔV _{IO})	V _{DD} = 2.7 V to 8 V, V _{IC} = V _{DD} /2, No load		25°C		80	95	dB
				Full range		80		
I _{DD}	Supply current (per channel)	V _O = 1.5 V, No load		25°C		725	1100	μA
				Full range		1100		

(1) Full range is –40°C to 125°C.

(2) Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at $T_A = 150^\circ\text{C}$ extrapolated to $T_A = 25^\circ\text{C}$ using the Arrhenius equation and assuming an activation energy of 0.96 eV.

OPERATING CHARACTERISTICS

$V_{DD} = 3\text{ V}$, at specified free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A ⁽¹⁾	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V _O = 1 V to 2 V, R _L = 600 Ω, C _L = 100 pF		25°C	0.65	1.3		V/μs
				Full range	0.4			
V _n	Equivalent input noise voltage	f = 10 Hz		25°C		170		nV/√Hz
		f = 1 kHz				18		
V _{n(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C		2.6		μV
		f = 0.1 Hz to 10 Hz				5.1		
I _n	Equivalent input noise current			25°C		0.6		fA/√Hz
THD+N	Total harmonic distortion plus noise	V _O = 0.5 V to 2.5 V, R _L = 600 Ω, f = 1 kHz	A _V = 1	25°C		0.08		%
			A _V = 10			0.3		
			A _V = 100			2		
	Gain-bandwidth product	f = 10 kHz, R _L = 600 Ω, C _L = 100 pF		25°C		1.75		MHz
BOM	Maximum output-swing bandwidth	V _{O(PP)} = 1 V, R _L = 600 Ω, A _V = 1, C _L = 100 pF		25°C		0.9		MHz
t _s	Settling time	A _V = −1, Step = −2.3 V to 2.3 V, R _L = 600 Ω, C _L = 100 pF	To 0.1%	25°C		1.5		μs
			To 0.01%			3.2		
φ _m	Phase margin at unity gain	R _L = 600 Ω, C _L = 100 pF		25°C		65		°
	Gain margin	R _L = 600 Ω, C _L = 100 pF		25°C		9		dB

(1) Full range is -40°C to 125°C .

ELECTRICAL CHARACTERISTICS

 $V_{DD} = 5\text{ V}$, at specified free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$T_A^{(1)}$	MIN	TYP	MAX	UNIT
V_{IO} Input offset voltage	$V_{DD\pm} = \pm 2.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$	TLV244x	25°C	300	2000	μV
		TLV244xA	Full range		2500	
			25°C	300	950	
			Full range		1600	
α_{VIO} Temperature coefficient of input offset voltage	$V_{DD\pm} = \pm 2.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$	25°C to 85°C		2		$\mu\text{V}/^\circ\text{C}$
Input offset voltage long-term drift ⁽²⁾	$V_{DD\pm} = \pm 2.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$	25°C		0.002		$\mu\text{V}/\text{mo}$
I_{IO} Input offset current	$V_{DD\pm} = \pm 2.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$	25°C		0.5		pA
		Full range			150	
I_{IB} Input bias current	$V_{DD\pm} = \pm 2.5\text{ V}$, $V_{IC} = 0$, $V_O = 0$, $R_S = 50\ \Omega$	25°C		1		pA
		Full range			260	
V_{ICR} Common-mode input voltage range	$ V_{IO} \leq 5\text{ mV}$, $R_S = 50\ \Omega$	25°C	0 to 4.25	–0.25 to 4.5		V
		Full range	0 to 4			
V_{OH} High-level output voltage	$I_{OH} = -100\ \mu\text{A}$ $I_{OH} = -5\text{ mA}$	25°C		4.97		V
		25°C	4	4.35		
		Full range	4			
V_{OL} Low-level output voltage	$V_{IC} = 2.5\text{ V}$	$I_{OL} = 100\ \mu\text{A}$	25°C		0.01	V
		$I_{OL} = 5\text{ mA}$	25°C		0.8	
			Full range		1.25	
A_{VD} Large-signal differential voltage amplification	$V_{IC} = 2.5\text{ V}$, $V_O = 1\text{ V to }4\text{ V}$	$R_L = 600\ \Omega^{(3)}$	25°C	0.9	1.3	V/mV
		$R_L = 1\text{ M}\Omega^{(3)}$	Full range	0.5		
			25°C		950	
r_{id} Differential input resistance		25°C		1000		$\text{G}\Omega$
r_i Common-mode input resistance		25°C		1000		$\text{G}\Omega$
c_i Common-mode input capacitance	$f = 10\text{ kHz}$	25°C		8		pF
z_o Closed-loop output impedance	$f = 1\text{ MHz}$, $A_V = 10$	25°C		140		Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR}\text{ MIN}$, $V_O = V_{DD}/2$, $R_S = 50\ \Omega$	25°C	70	75		dB
		Full range	70			
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{DD}/\Delta V_{IO}$)	$V_{DD} = 4.4\text{ V to }8\text{ V}$, $V_{IC} = V_{DD}/2$, No load	25°C	80	95		dB
		Full range	80			
I_{DD} Supply current (per channel)	$V_O = 2.5\text{ V}$, No load	25°C		750	1100	μA
		Full range			1100	

(1) Full range is -40°C to 125°C .

(2) Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at $T_A = 150^\circ\text{C}$ extrapolated to $T_A = 25^\circ\text{C}$ using the Arrhenius equation and assuming an activation energy of 0.96 eV.

(3) Referenced to 2.5 V

OPERATING CHARACTERISTICS

$V_{DD} = 5\text{ V}$, at specified free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A ⁽¹⁾	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V _O = 0.5 V to 2.5 V, R _L = 600 Ω ⁽²⁾ , C _L = 100 pF ⁽²⁾		25°C	0.75	1.4		V/μs
				Full range	0.5			
V _n	Equivalent input noise voltage	f = 10 Hz		25°C		130		nV/√Hz
		f = 1 kHz				16		
V _{n(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C		1.8		μV
		f = 0.1 Hz to 10 Hz				3.6		
I _n	Equivalent input noise current			25°C		0.6		fA/√Hz
THD+N	Total harmonic distortion plus noise	V _O = 1.5 V to 3.5V, f = 1 kHz, R _L = 600 Ω ⁽²⁾	A _V = 1	25°C		0.017		%
			A _V = 10			0.17		
			A _V = 100			1.5		
	Gain-bandwidth product	f = 10 kHz, R _L = 600 Ω ⁽²⁾ , C _L = 100 pF ⁽²⁾		25°C		1.81		MHz
BOM	Maximum output-swing bandwidth	V _{O(PP)} = 2 V, A _V = 1, R _L = 600 Ω ⁽²⁾ , C _L = 100 pF ⁽²⁾		25°C		0.5		MHz
t _s	Settling time	A _V = −1, Step = −0.5 V to 2.5 V, R _L = 600 Ω ⁽²⁾ , C _L = 100 pF ⁽²⁾	To 0.1%	25°C		1.5		μs
			To 0.01%			2.6		
φ _m	Phase margin at unity gain	R _L = 600 Ω ⁽²⁾ , C _L = 100 pF ⁽²⁾		25°C		68		°
	Gain margin	R _L = 600 Ω ⁽²⁾ , C _L = 100 pF ⁽²⁾		25°C		8		dB

(1) Full range is -40°C to 125°C .

(2) Referenced to 2.5 V

TYPICAL CHARACTERISTICS

Table of Graphs⁽¹⁾

			FIGURE
V_{IO}	Input offset voltage	Distribution	2, 3
		vs Common-mode input voltage	4, 5
α_{VIO}	Input offset voltage temperature coefficient	Distribution	6, 7
I_B/I_{IO}	Input bias and input offset currents	vs Free-air temperature	8
V_{OH}	High-level output voltage	vs High-level output current	9, 10
V_{OL}	Low-level output voltage	vs Low-level output current	11, 12
$V_{O(PP)}$	Maximum peak-to-peak output voltage	vs Frequency	13
I_{OS}	Short-circuit output current	vs Supply voltage	14
		vs Free-air temperature	15
V_O	Output voltage	vs Differential input voltage	16, 17
A_{VD}	Differential voltage amplification	vs Load resistance	18
	Large-signal differential voltage amplification and phase margin	vs Frequency	19, 20
	Large-signal differential voltage amplification	vs Free-air temperature	21, 22
z_o	Output impedance	vs Frequency	23, 24
CMRR	Common-mode rejection ratio	vs Frequency	25
		vs Free-air temperature	26
k_{SVR}	Supply-voltage rejection ratio	vs Frequency	27, 28
		vs Free-air temperature	29
I_{DD}	Supply current	vs Supply voltage	30
SR	Slew rate	vs Load capacitance	31
		vs Free-air temperature	32
V_O	Inverting large-signal pulse response		33, 34
	Voltage-follower large-signal pulse response		35, 36
	Inverting small-signal pulse response		37, 38
	Voltage-follower small-signal pulse response		39, 40
V_n	Equivalent input noise voltage	vs Frequency	41, 42
	Noise voltage	Over a 10-second period	43
THD + N	Total harmonic distortion plus noise	vs Frequency	44, 45
		vs Free-air temperature	46
		vs Supply voltage	47
ϕ_m	Phase margin	vs Frequency	19, 20
		vs Load capacitance	48
	Gain margin	vs Load capacitance	49
B_1	Unity-gain bandwidth	vs Load capacitance	50

(1) For all graphs where $V_{DD} = 5\text{ V}$, all loads are referenced to 2.5 V.

**DISTRIBUTION OF TLV2442
INPUT OFFSET VOLTAGE**

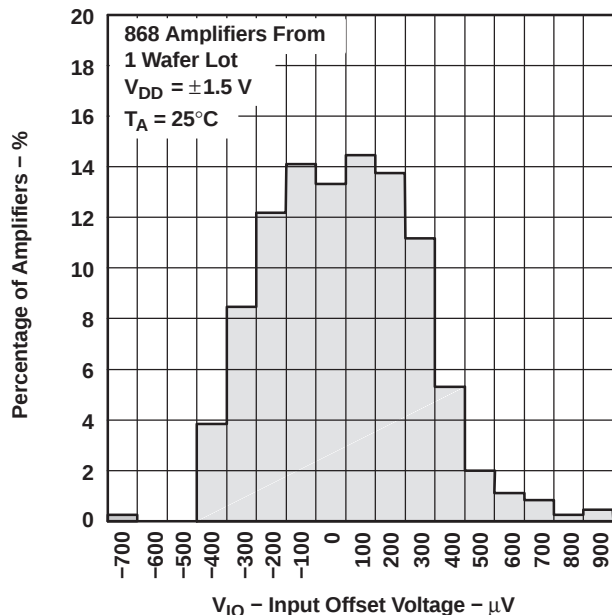


Figure 2.

INPUT OFFSET VOLTAGE

VS

COMMON-MODE INPUT VOLTAGE

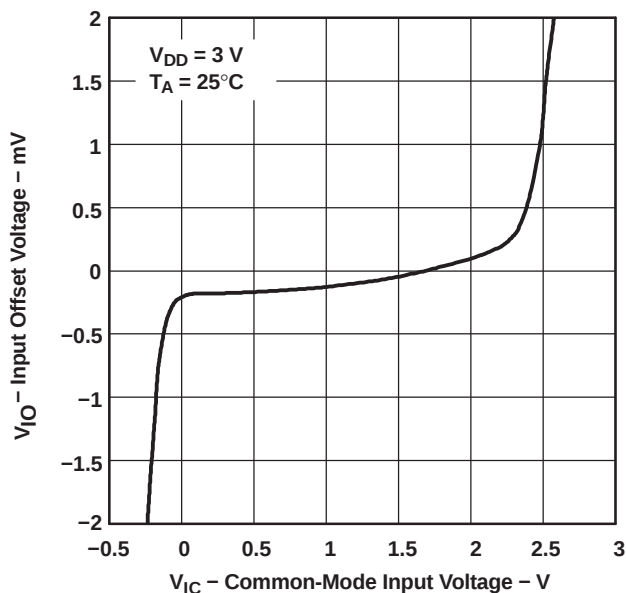


Figure 4.

**DISTRIBUTION OF TLV2442
INPUT OFFSET VOLTAGE**

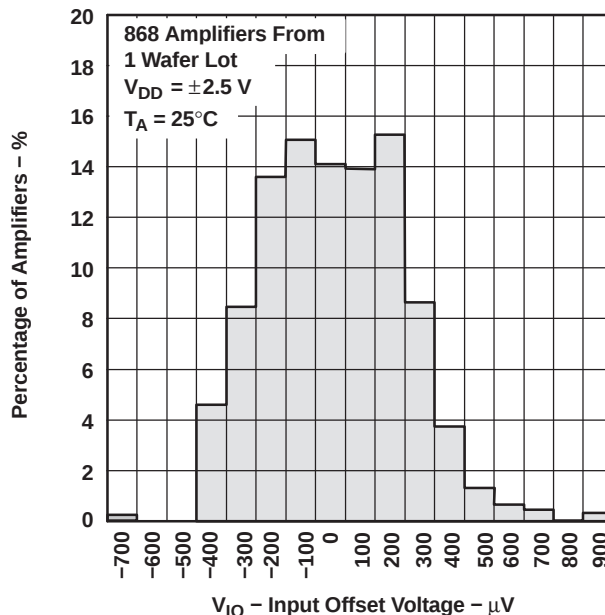


Figure 3.

INPUT OFFSET VOLTAGE

VS

COMMON-MODE INPUT VOLTAGE

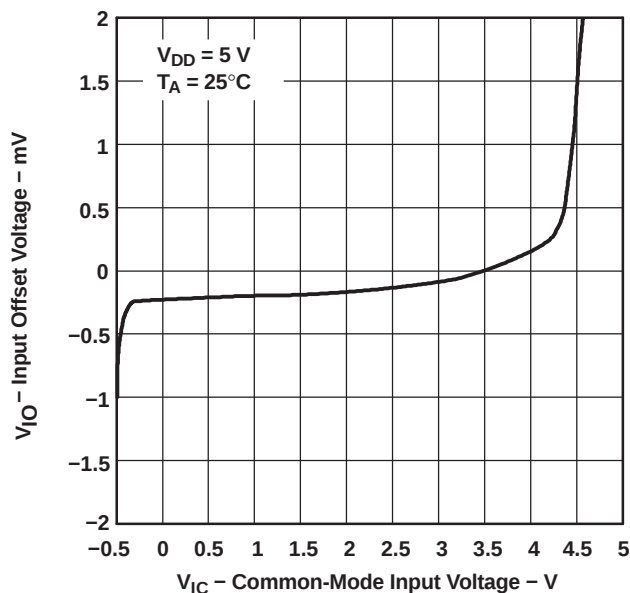


Figure 5.

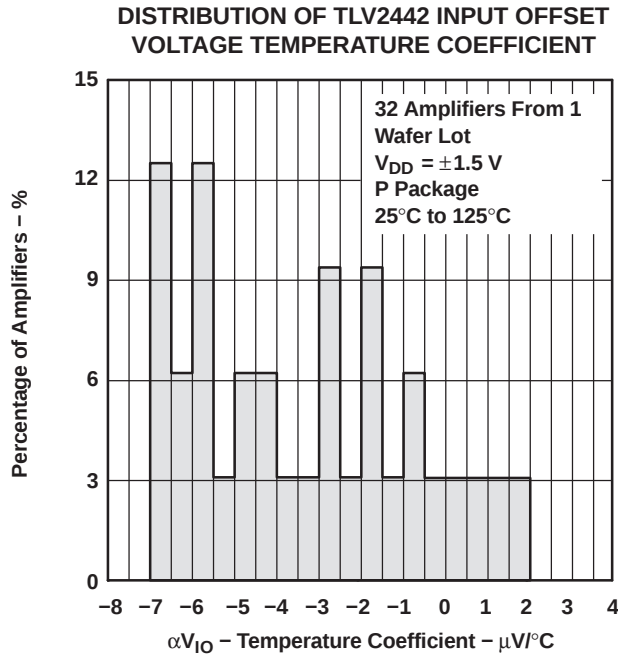


Figure 6.

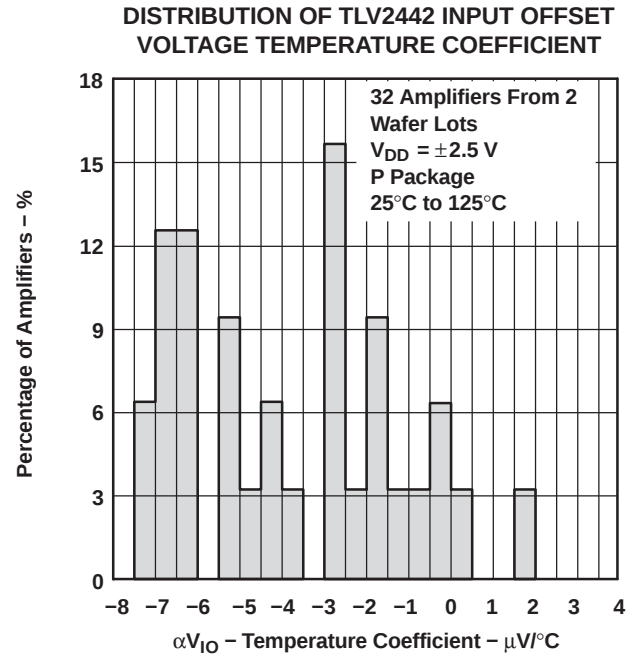


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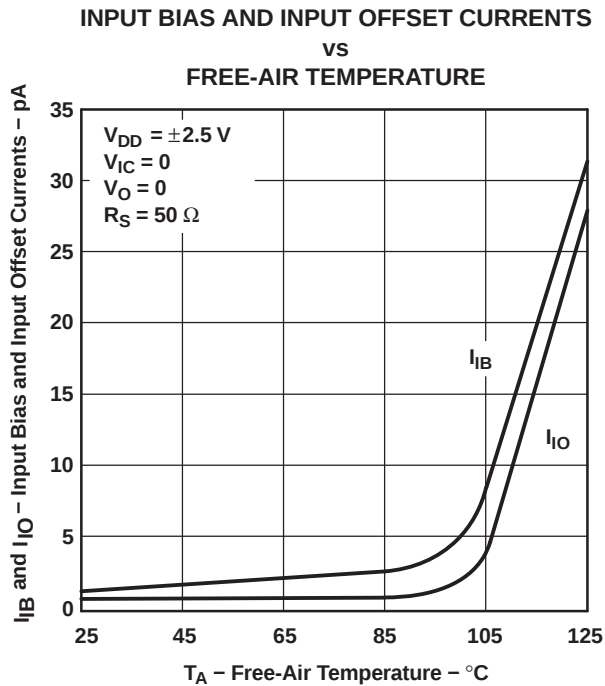


Figure 8.

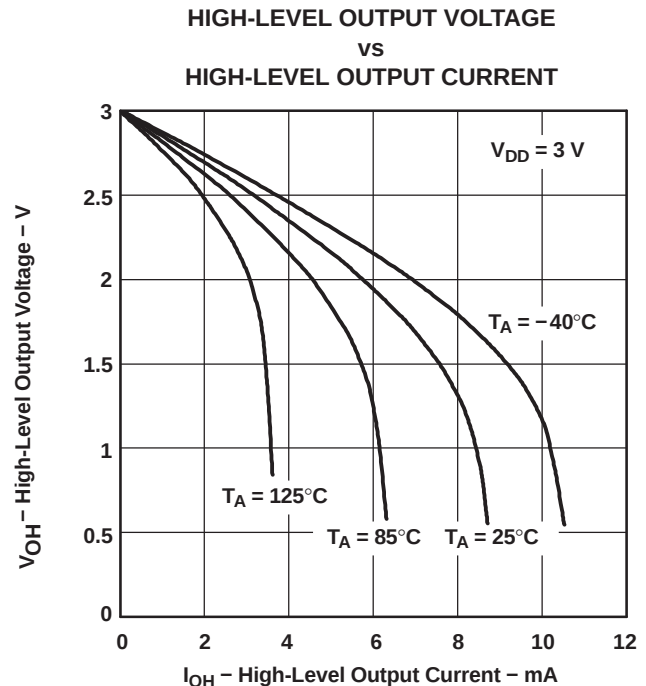
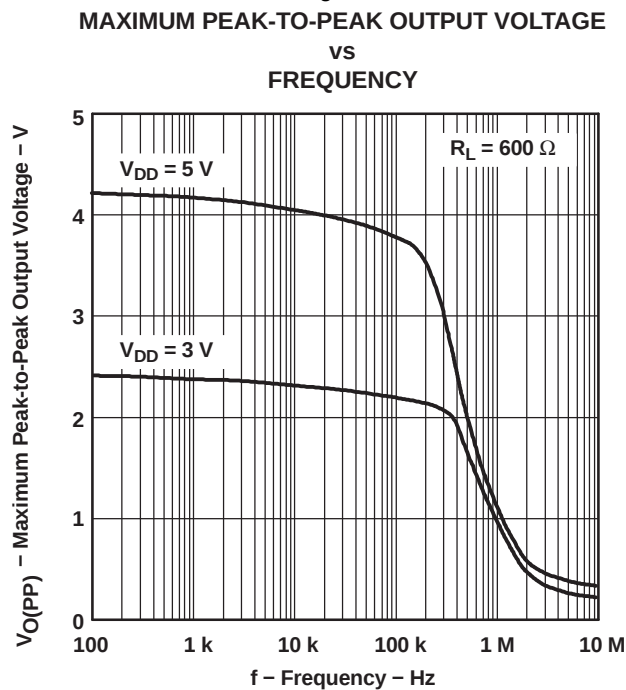
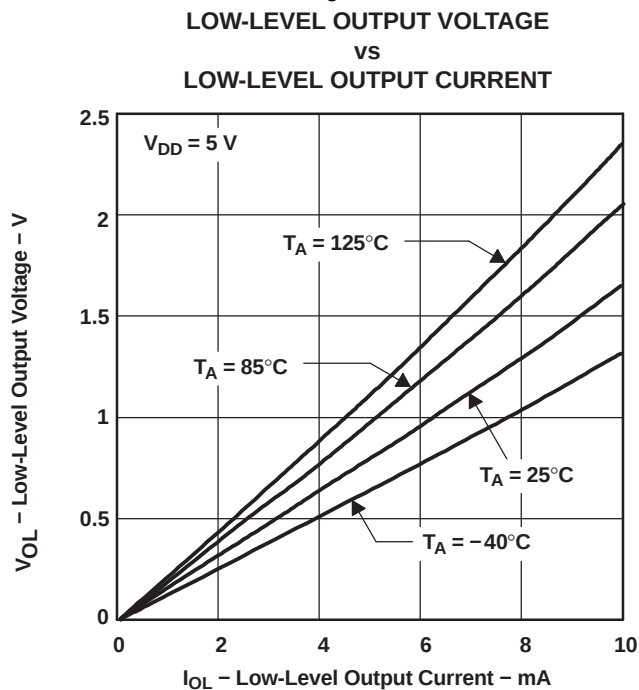
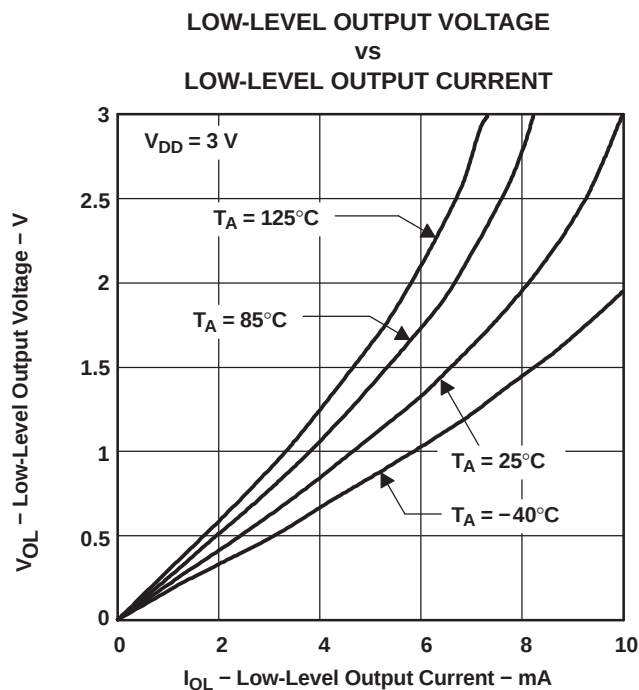
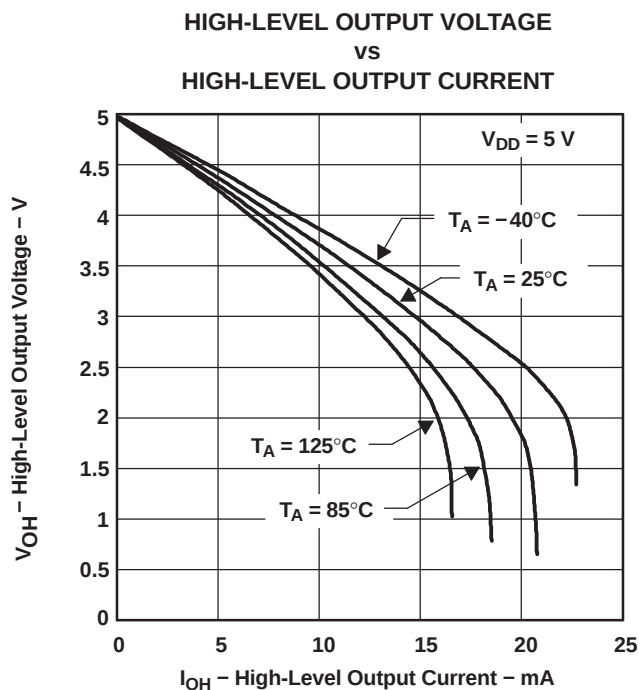
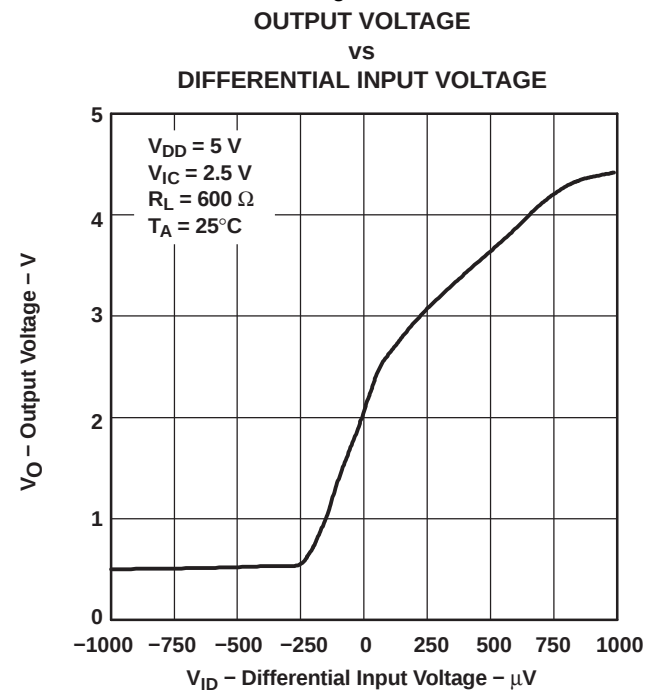
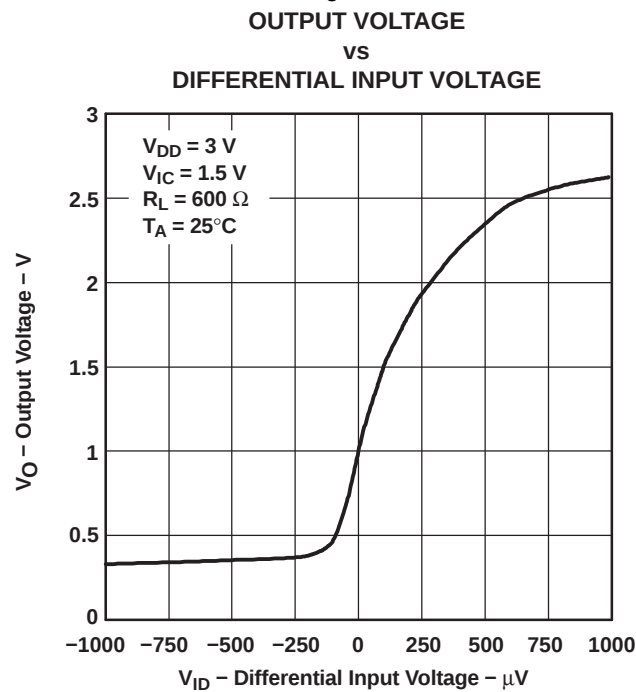
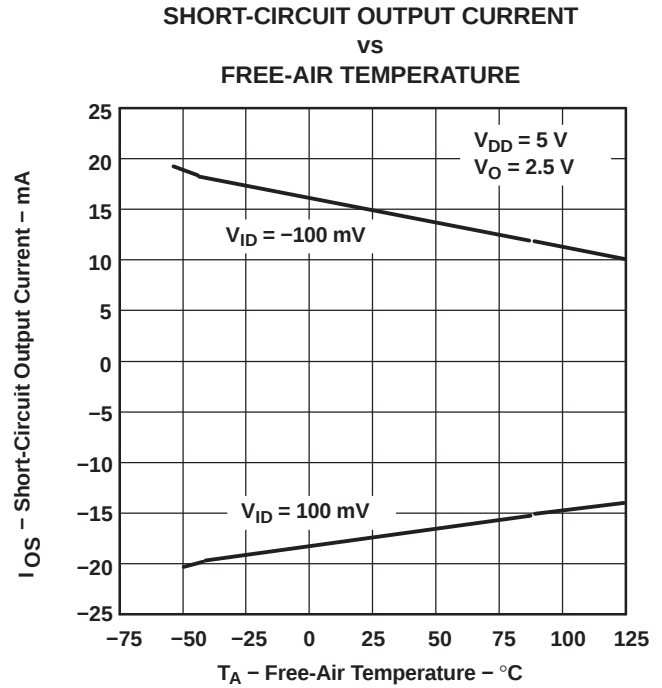
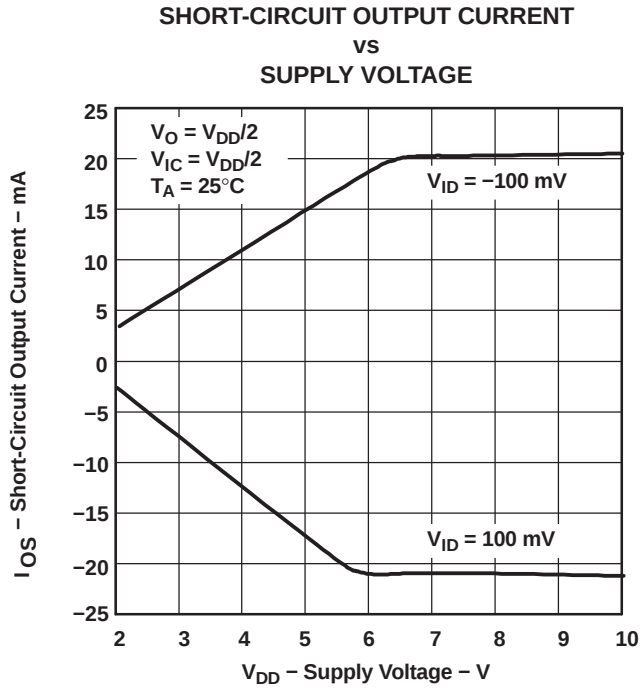


Figure 9.





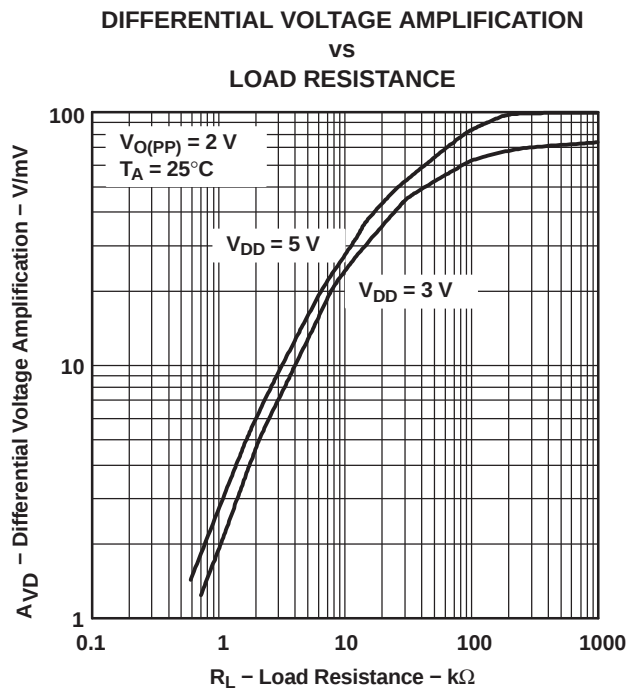


Figure 18.
**LARGE-SIGNAL DIFFERENTIAL VOLTAGE
AMPLIFICATION AND PHASE MARGIN
VS
FREQUENCY**

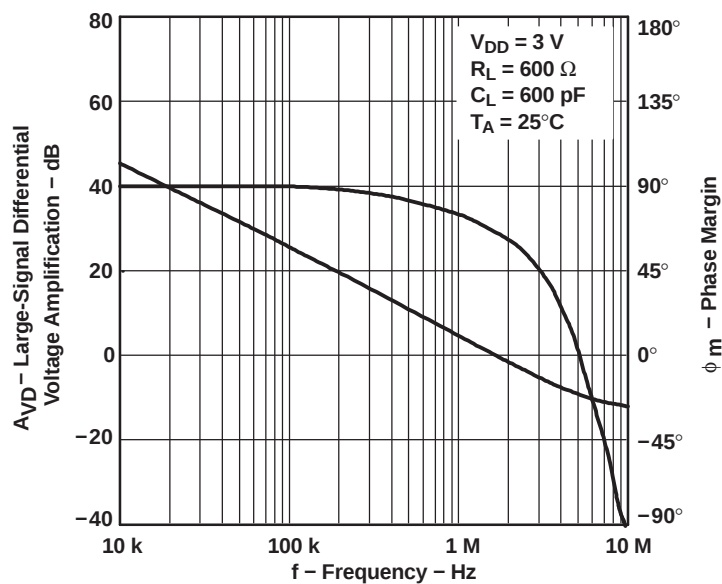


Figure 19.

LARGE-SIGNAL DIFFERENTIAL VOLTAGE
AMPLIFICATION AND PHASE MARGIN
vs
FREQUENCY

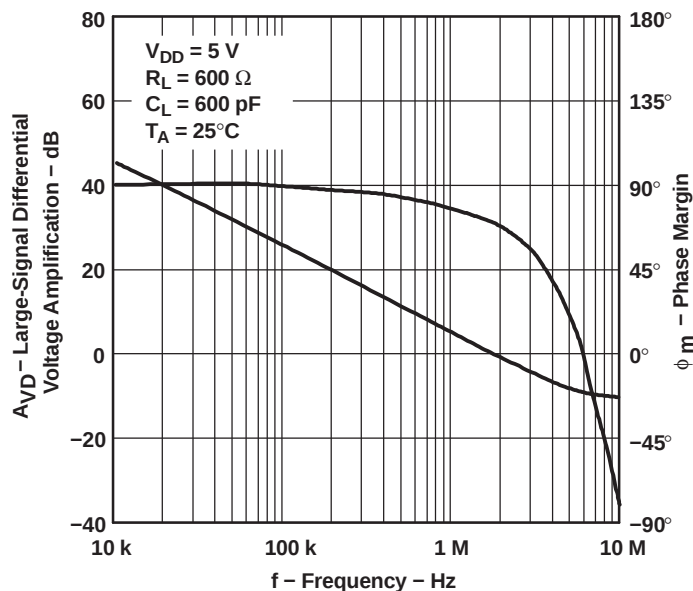


Figure 20.

LARGE-SIGNAL DIFFERENTIAL
VOLTAGE AMPLIFICATION
vs
FREE-AIR TEMPERATURE

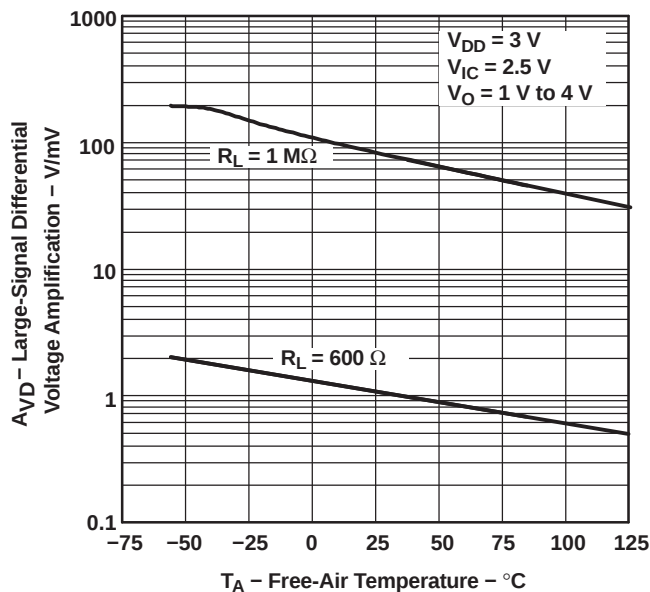


Figure 21.

LARGE-SIGNAL DIFFERENTIAL
VOLTAGE AMPLIFICATION
vs
FREE-AIR TEMPERATURE

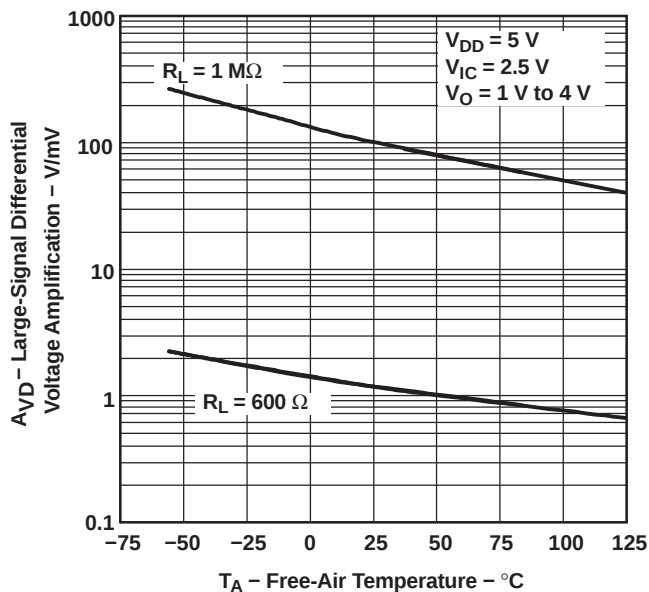


Figure 22.

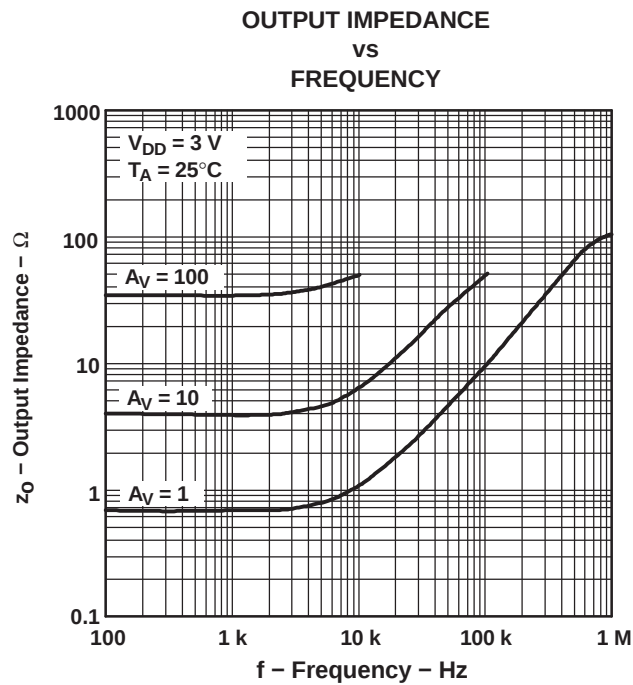


Figure 23.

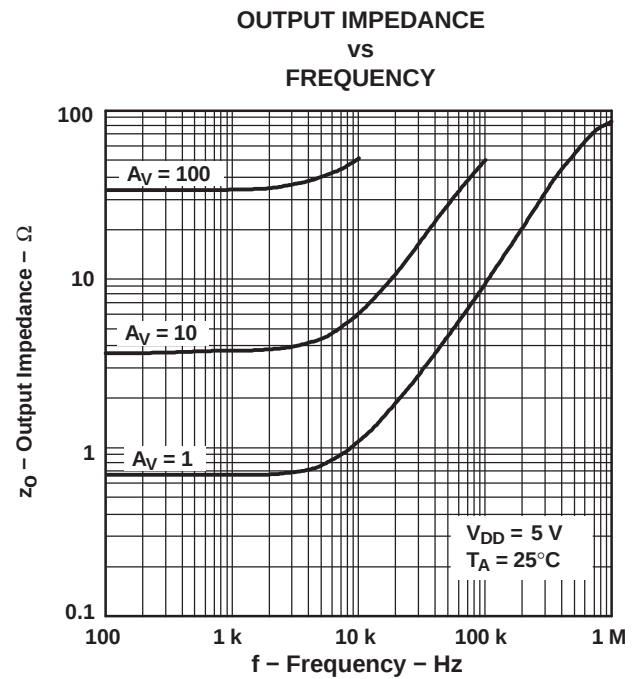


Figure 24.

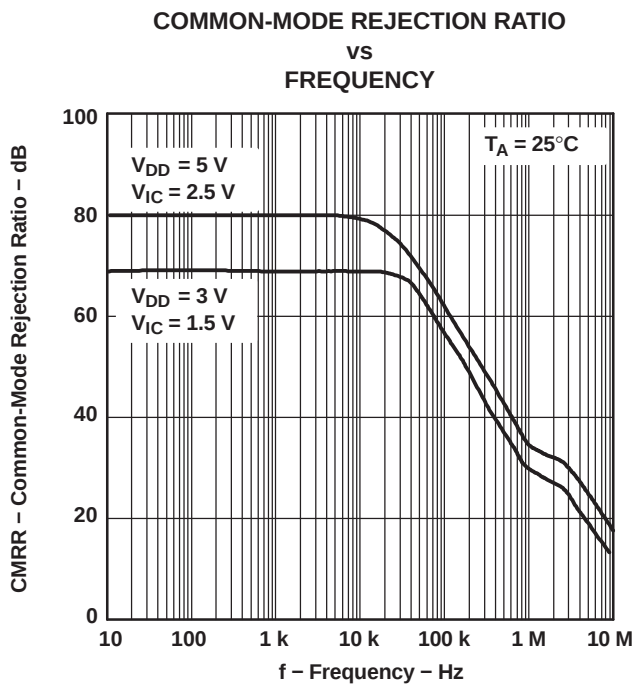


Figure 25.

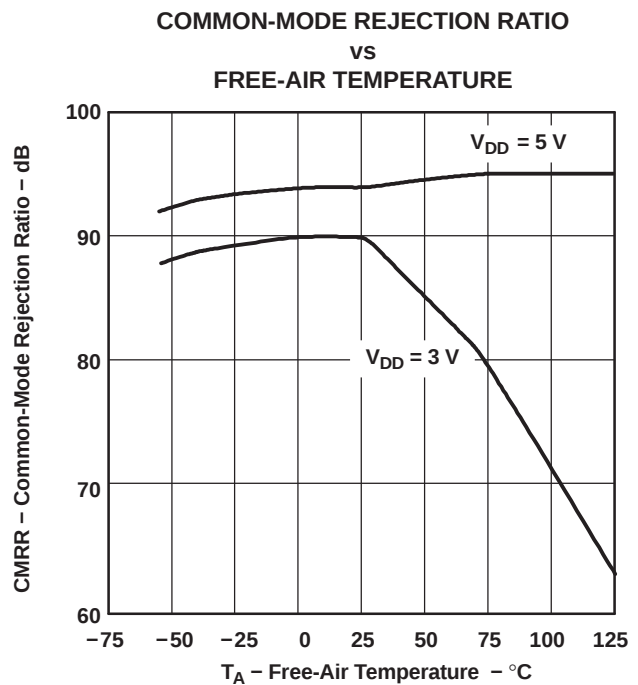


Figure 26.

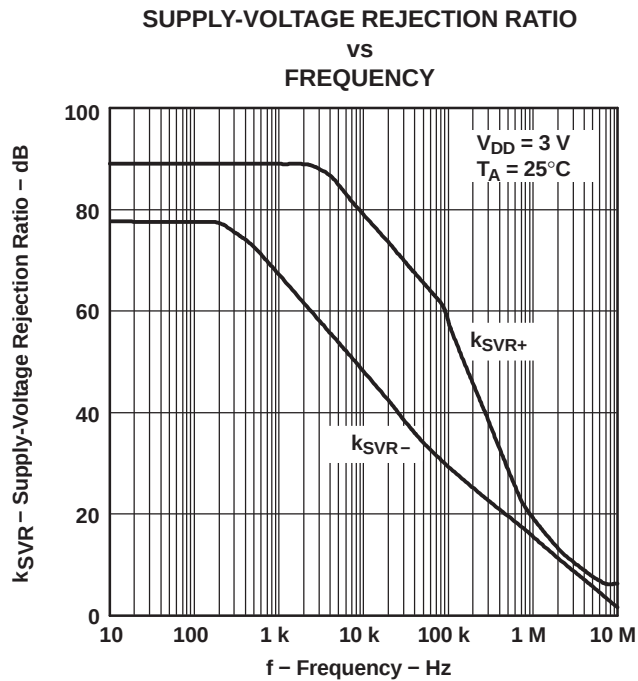


Figure 27.

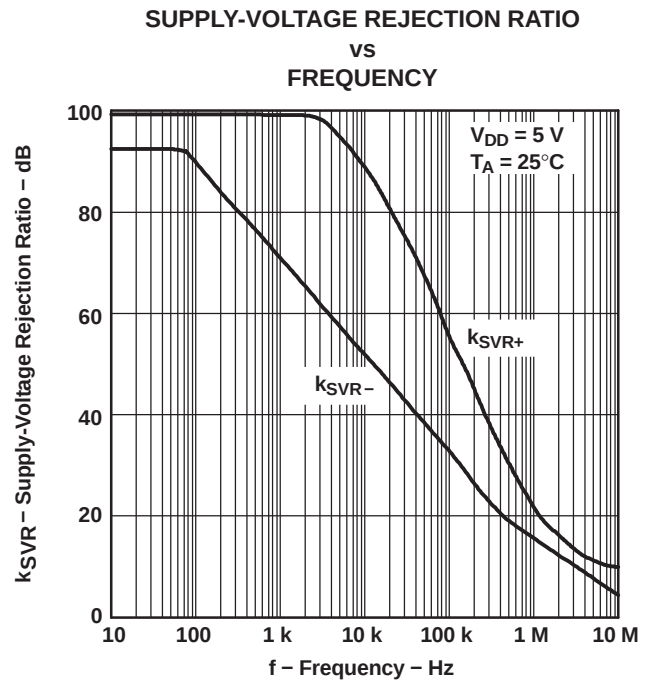


Figure 28.

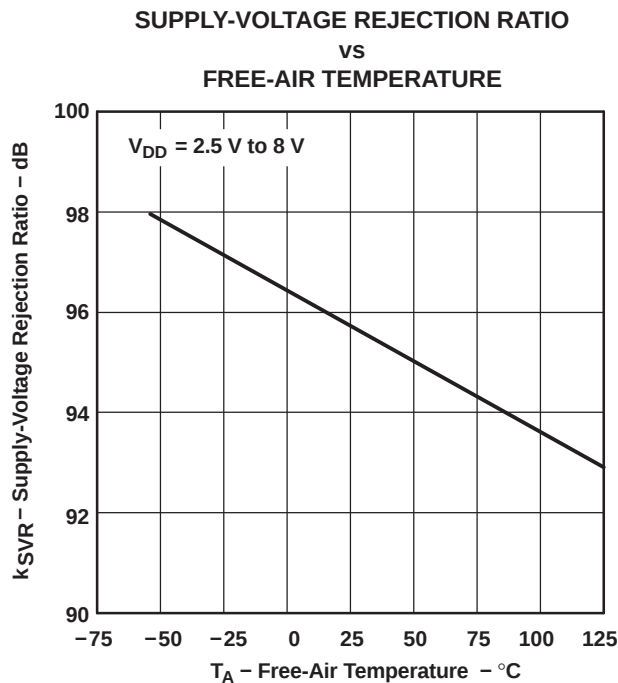


Figure 29.

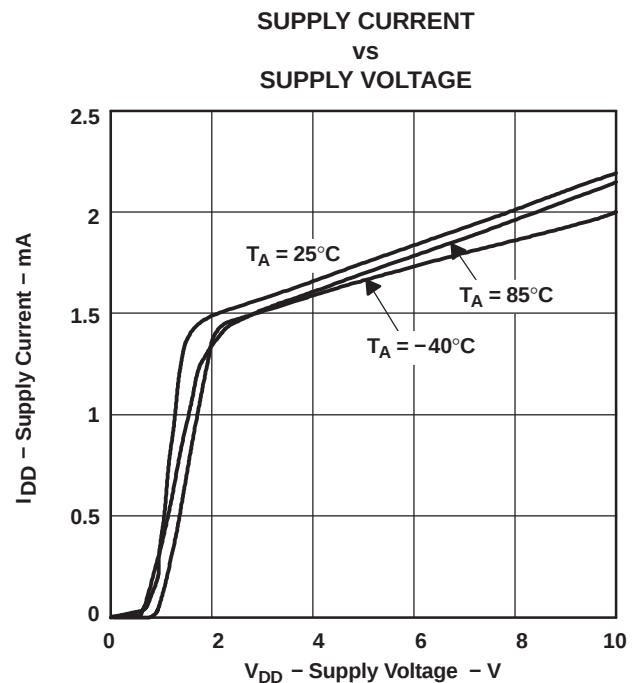


Figure 30.

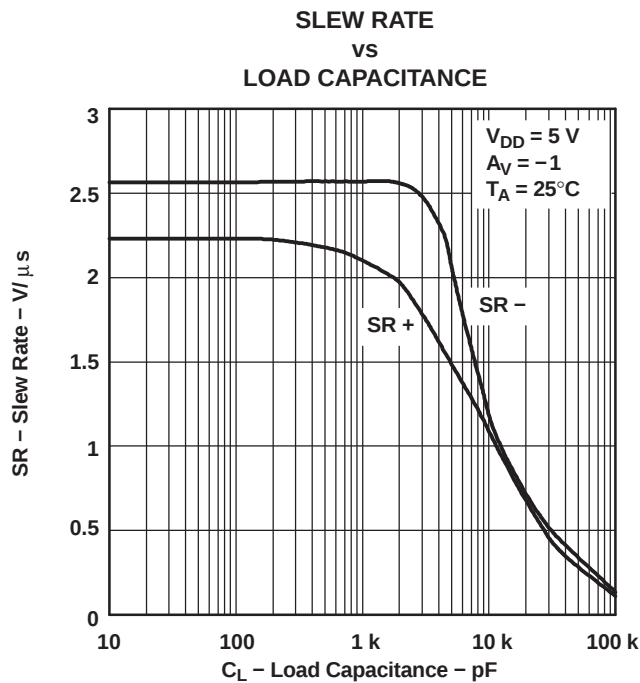


Figure 31.

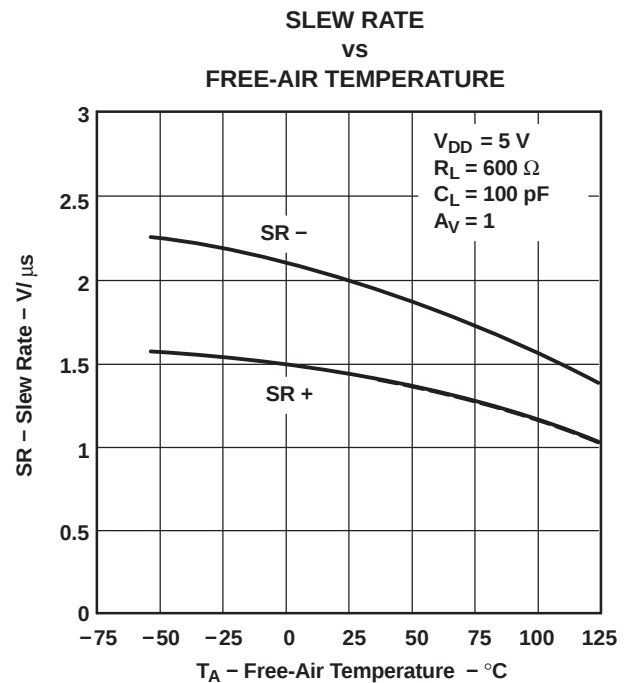


Figure 32.

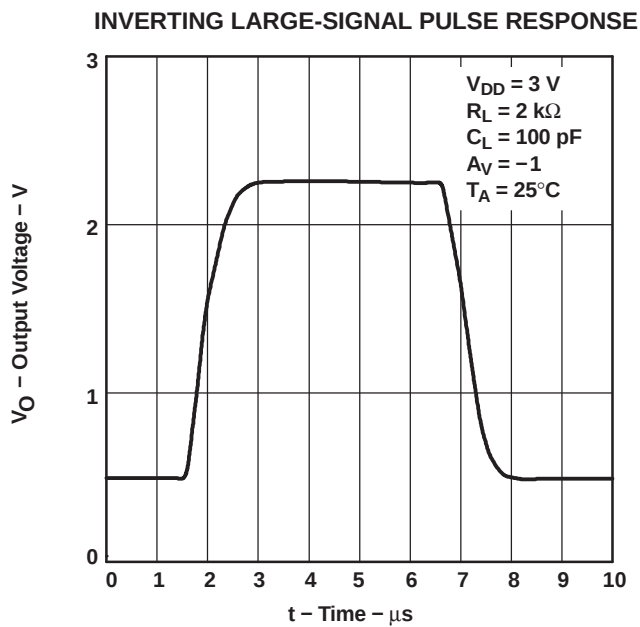


Figure 33.

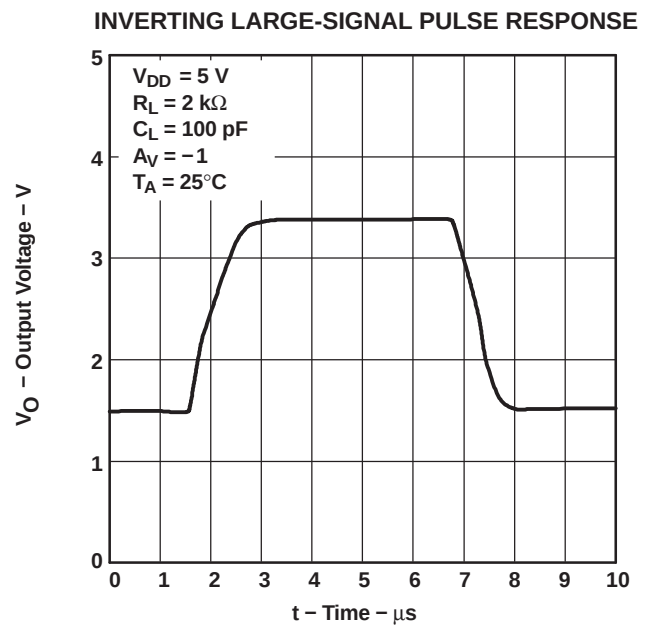


Figure 34.

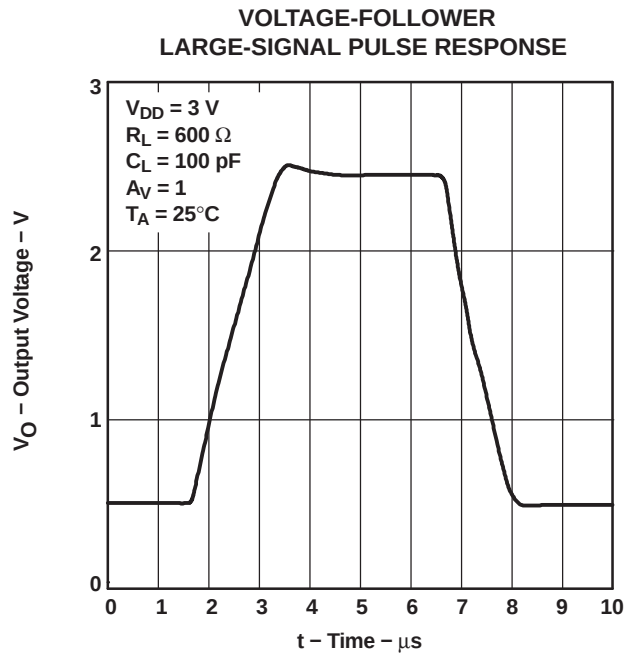


Figure 35.

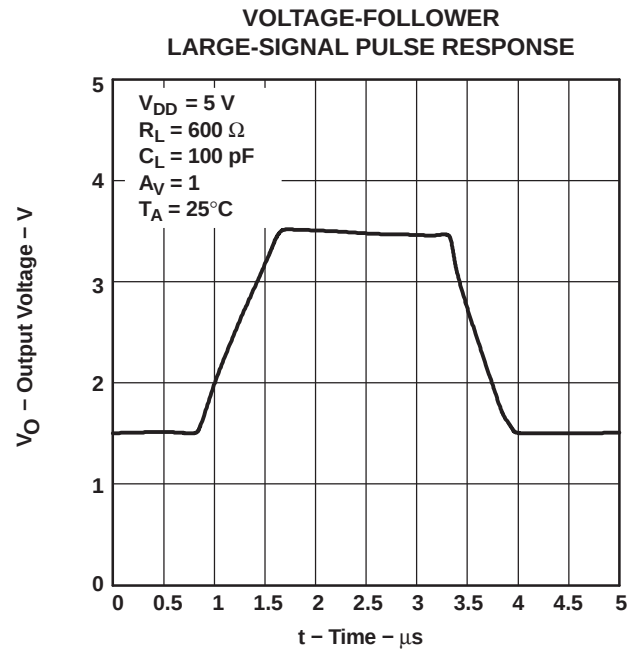


Figure 36.

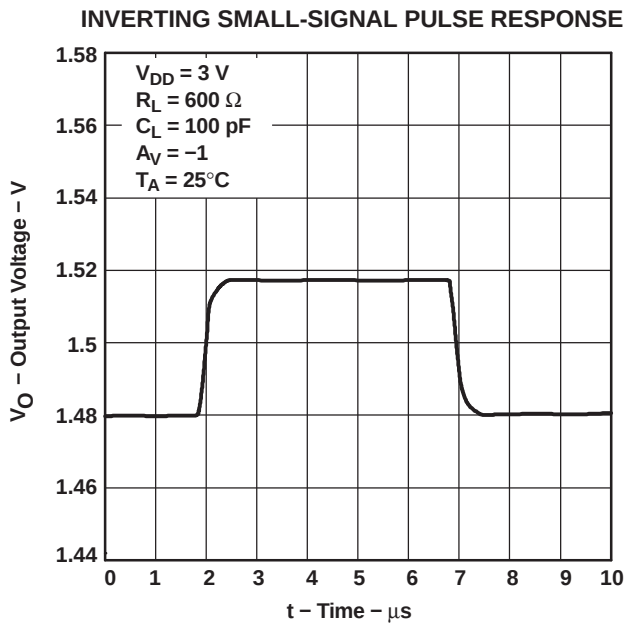


Figure 37.

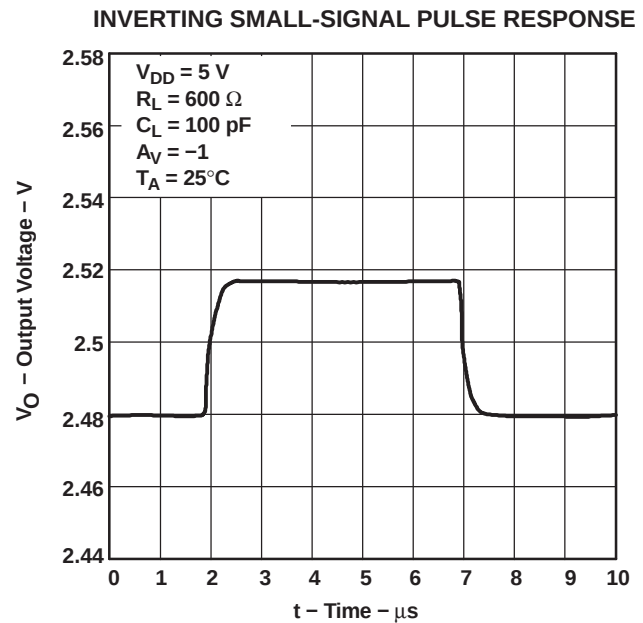


Figure 38.

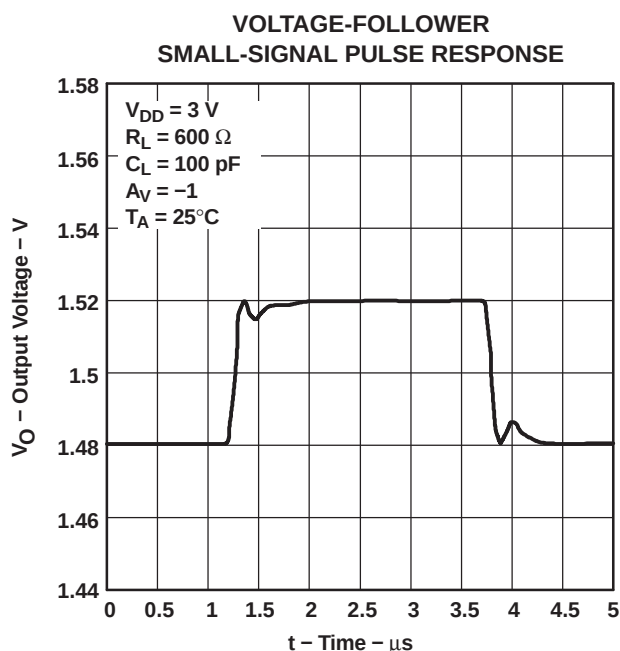


Figure 39.

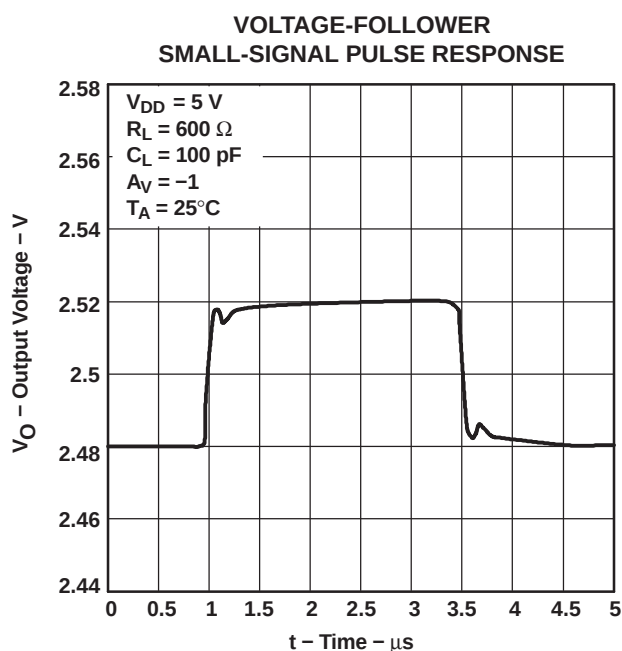


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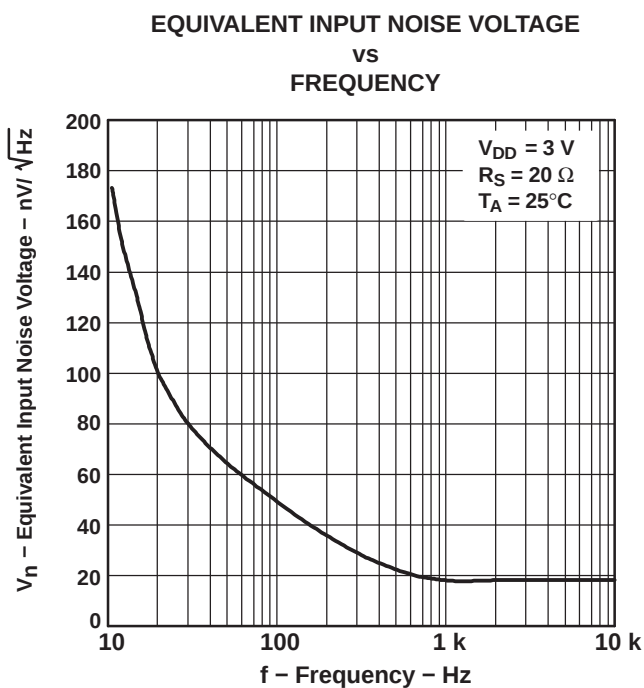


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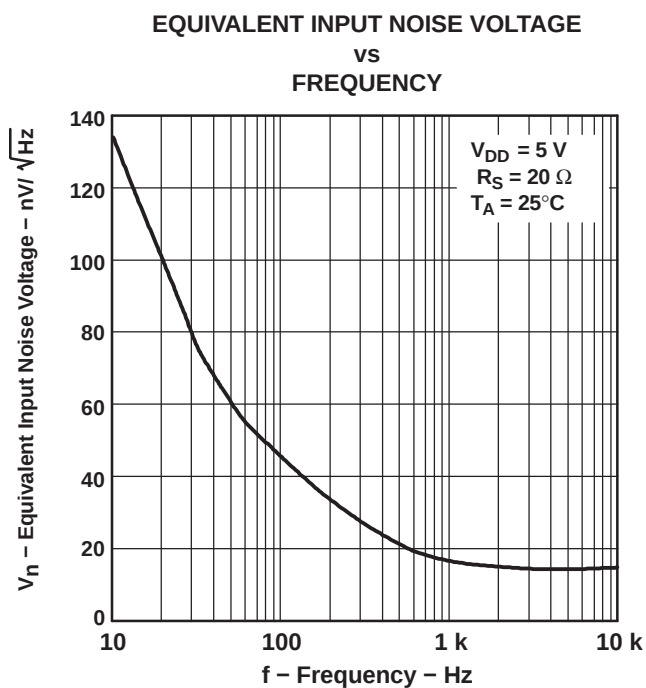


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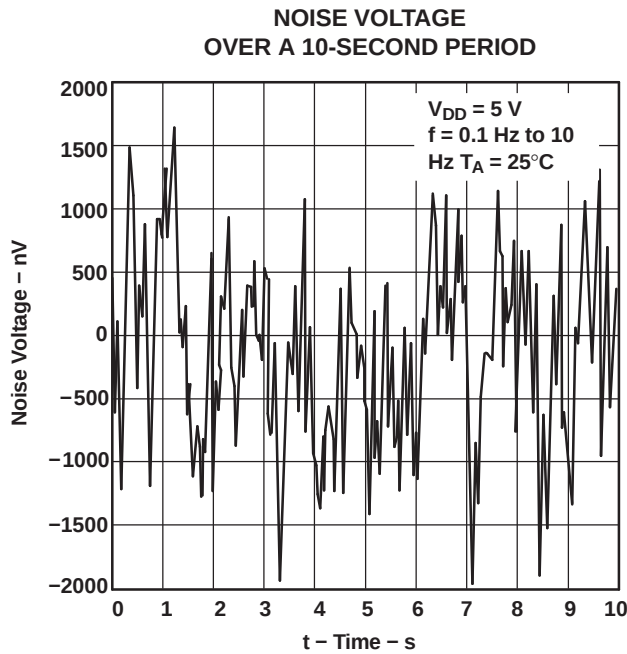


Figure 43.

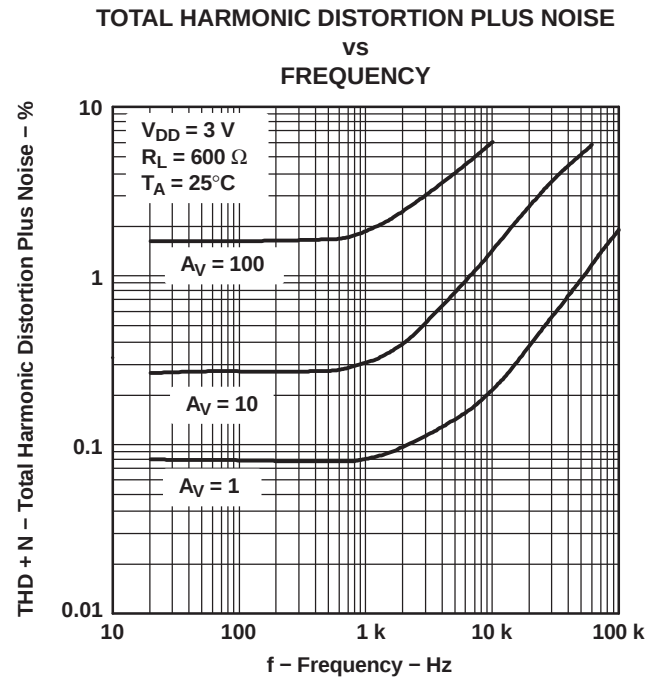


Figure 44.

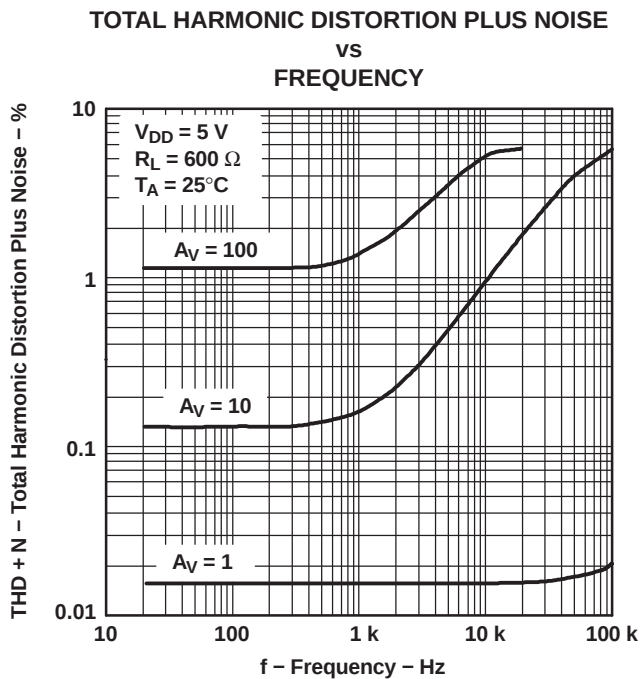


Figure 45.

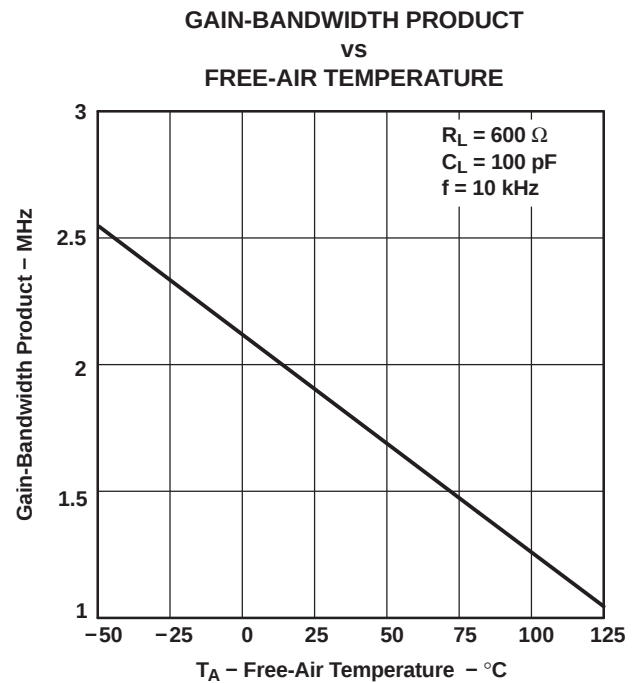


Figure 46.

**GAIN-BANDWIDTH PRODUCT
VS
SUPPLY VOLTAGE**

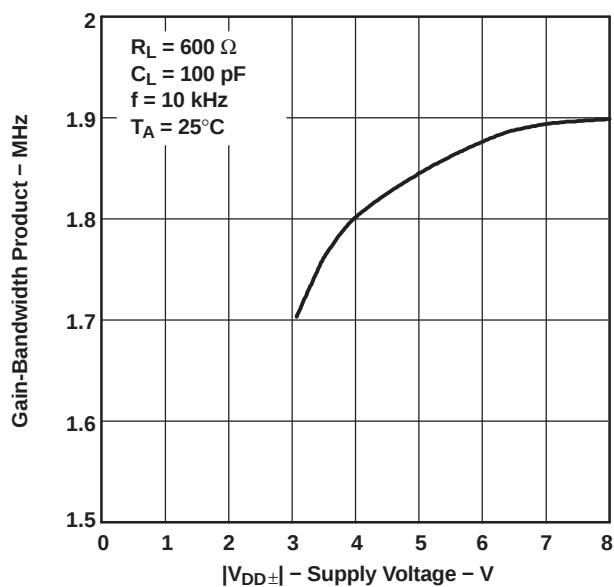


Figure 47.

**PHASE MARGIN
VS
LOAD CAPACITANCE**

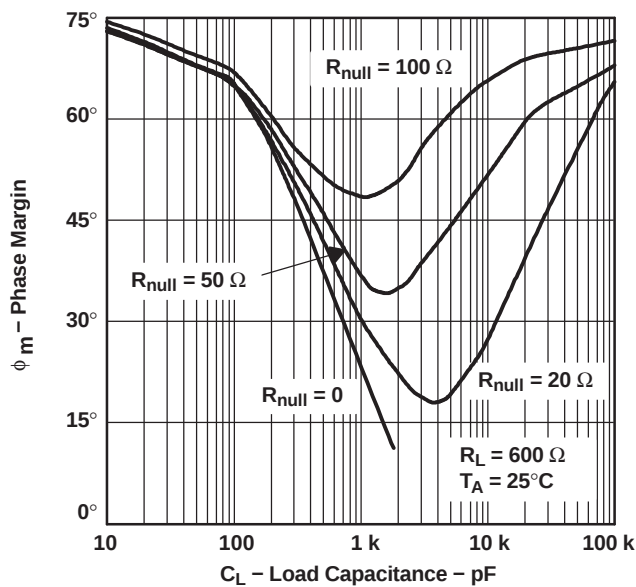


Figure 48.

**GAIN MARGIN
VS
LOAD CAPACITANCE**

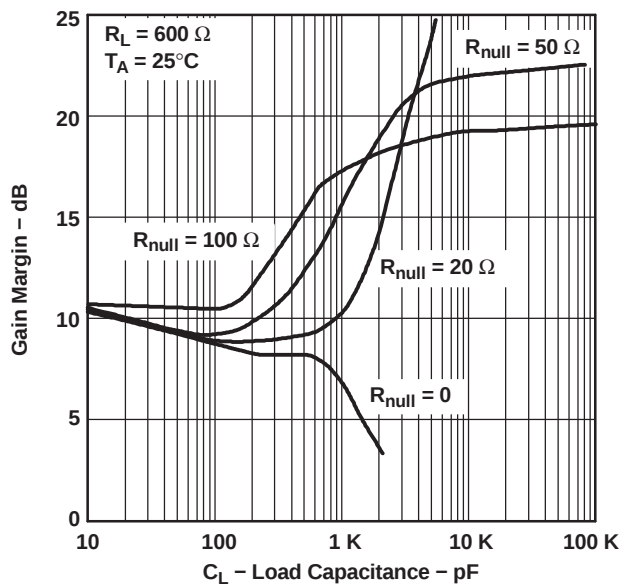


Figure 49.

**UNITY-GAIN BANDWIDTH
VS
LOAD CAPACITANCE**

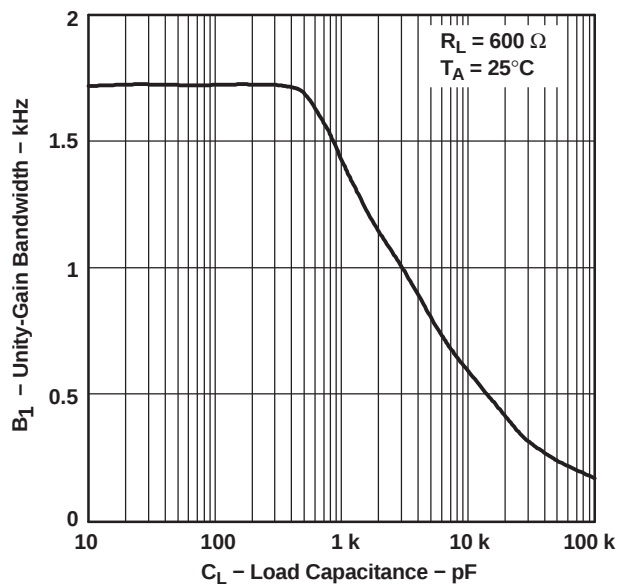


Figure 50.

APPLICATION INFORMATION

macromodel information

Macromodel information provided was derived using PSpice™ Parts™ model generation software. The Boyle macromodel⁽²⁾ and subcircuit in Figure 51 were generated using the TLV244x typical electrical and operating characteristics at $T_A = 25^\circ\text{C}$. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

(2) G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers," *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

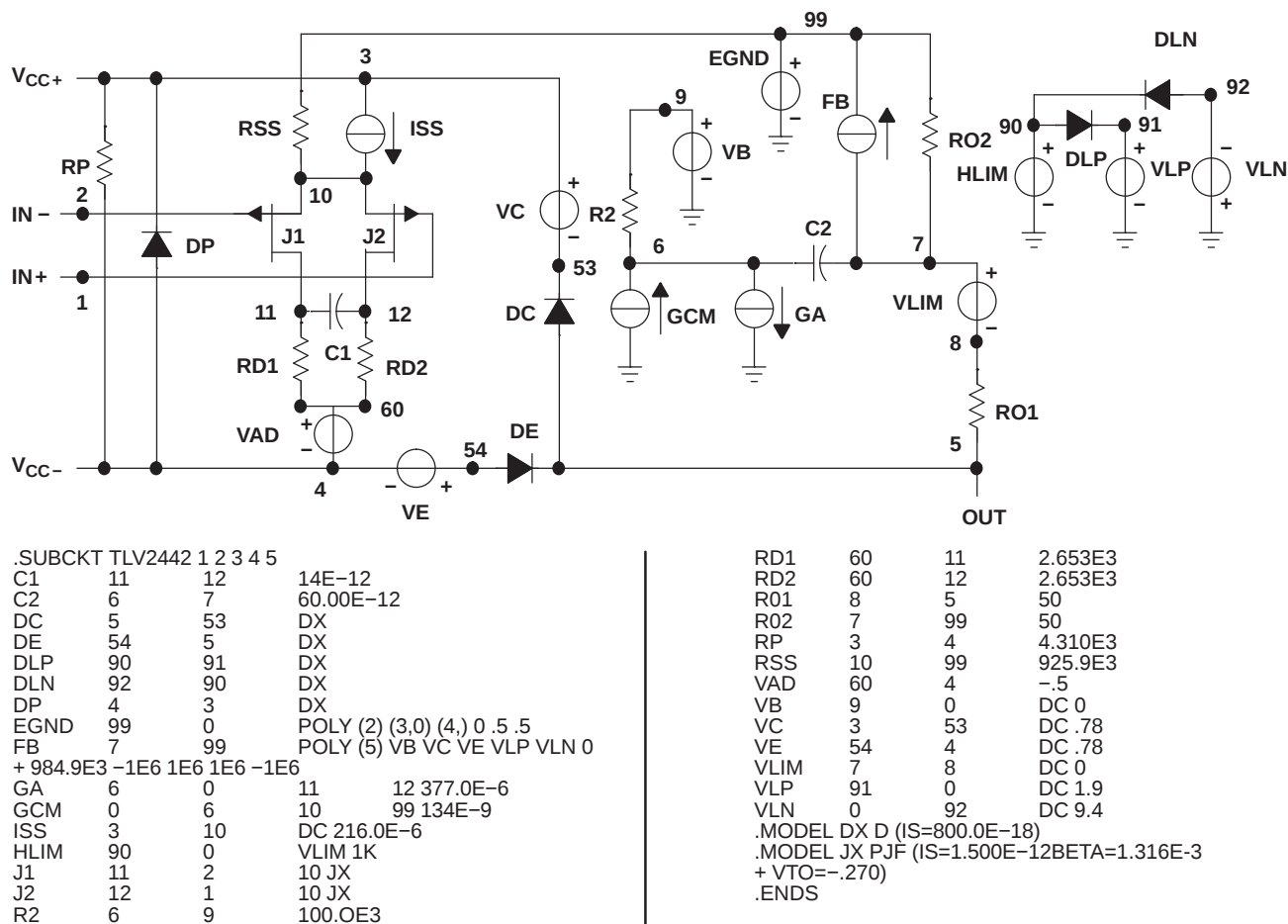


Figure 51. Boyle Macromodel and Subcircuit

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV2442AQDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2442AQ	Samples
TLV2442AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2442AQ	Samples
TLV2442AQPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2442AQ	Samples
TLV2442AQPWRQ1	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	-40 to 125		
TLV2442QDGKRQ1	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OBR	Samples
TLV2442QDRQ1	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		
TLV2442QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2442Q1	Samples
TLV2442QPWRQ1	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	-40 to 125		
TLV2444AQPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2444AQ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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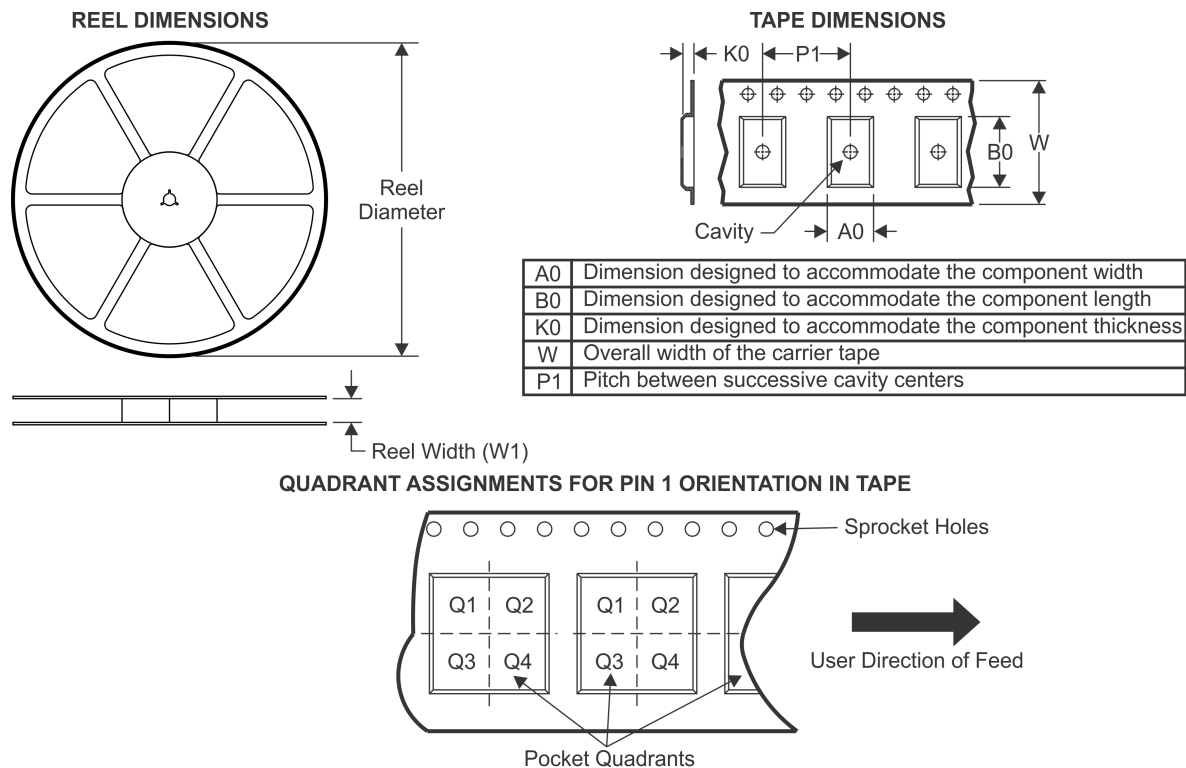
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TLV2442-Q1, TLV2442A-Q1, TLV2444A-Q1 :

- Catalog: [TLV2442](#), [TLV2442A](#), [TLV2444A](#)
- Military: [TLV2442M](#), [TLV2442AM](#)

NOTE: Qualified Version Definitions:

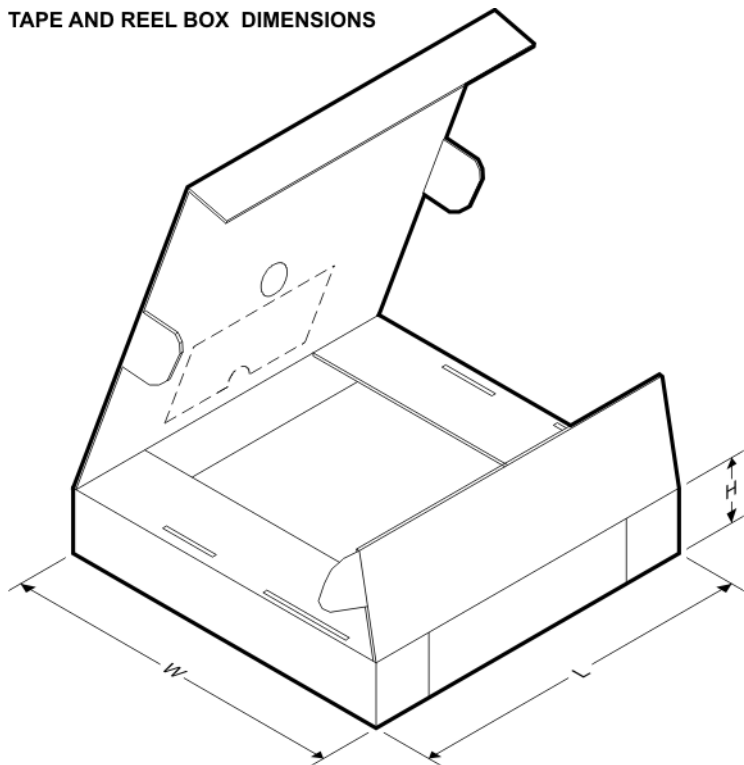
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV2442AQPWRG4Q1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLV2442QDGKRQ1	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TLV2442QPWRG4Q1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLV2444AQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

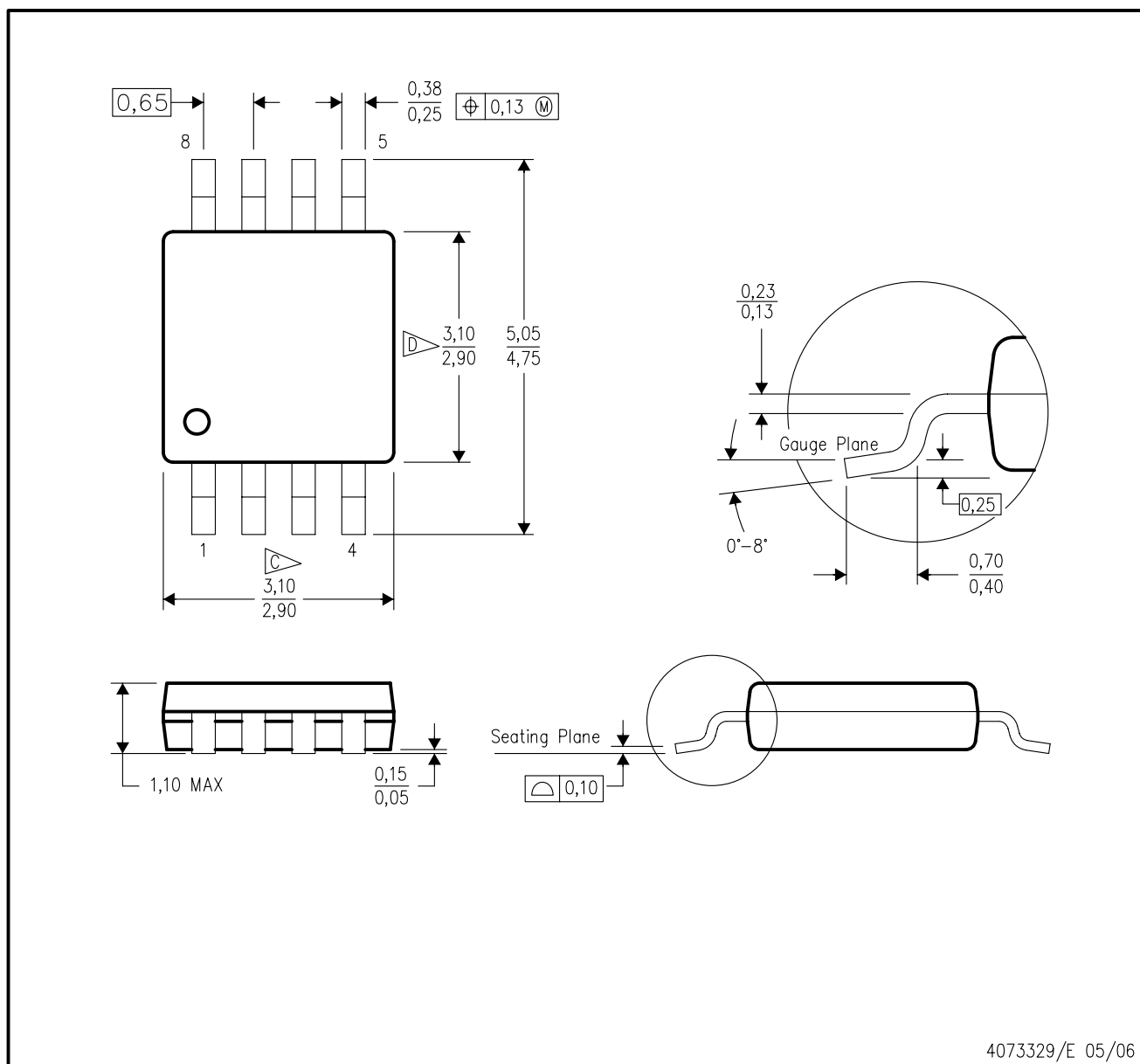


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV2442AQPWRG4Q1	TSSOP	PW	8	2000	367.0	367.0	35.0
TLV2442QDGKRQ1	VSSOP	DGK	8	2500	367.0	367.0	35.0
TLV2442QPWRG4Q1	TSSOP	PW	8	2000	367.0	367.0	35.0
TLV2444AQPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

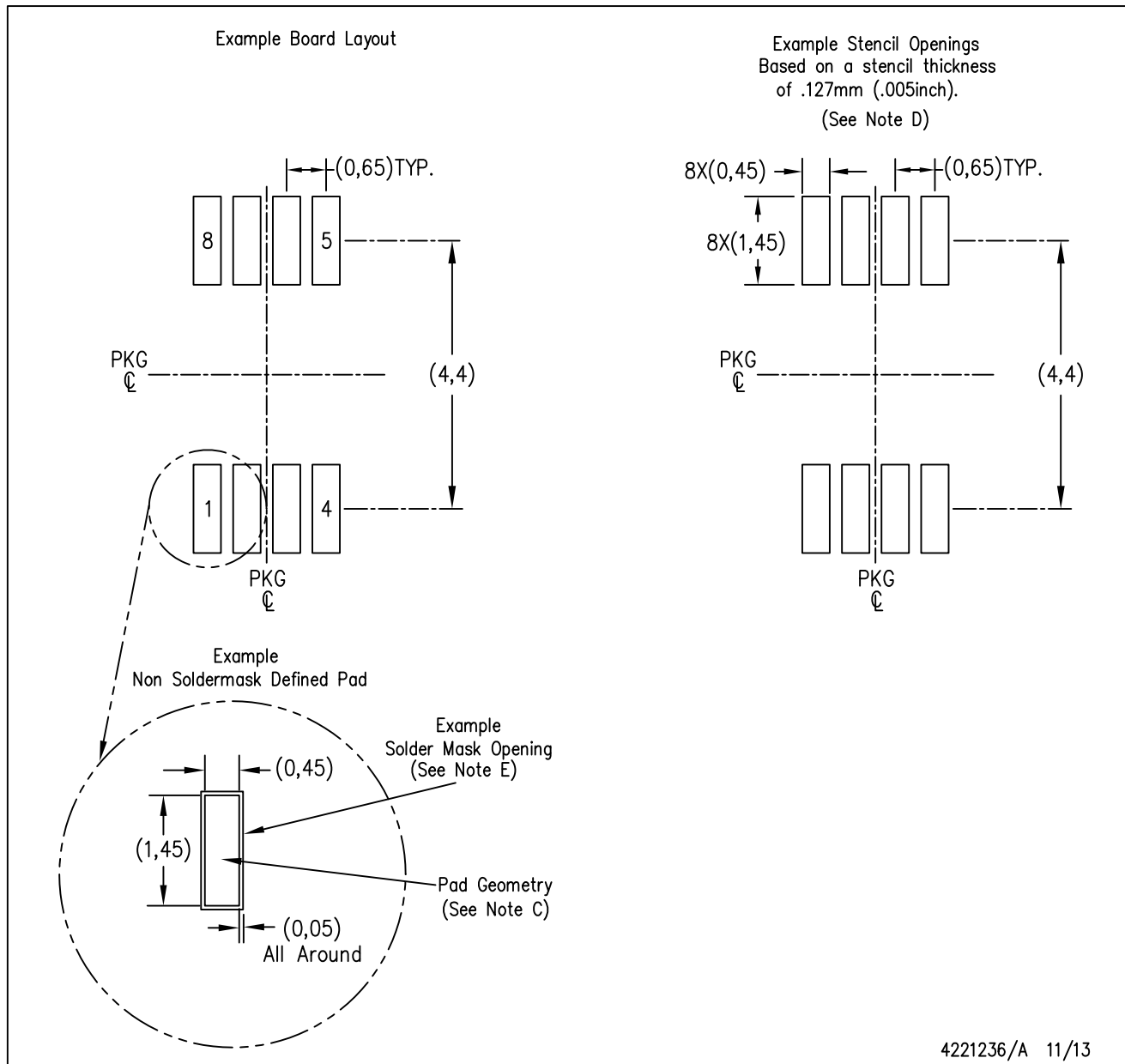


NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.

DGK (S-PDSO-G8)

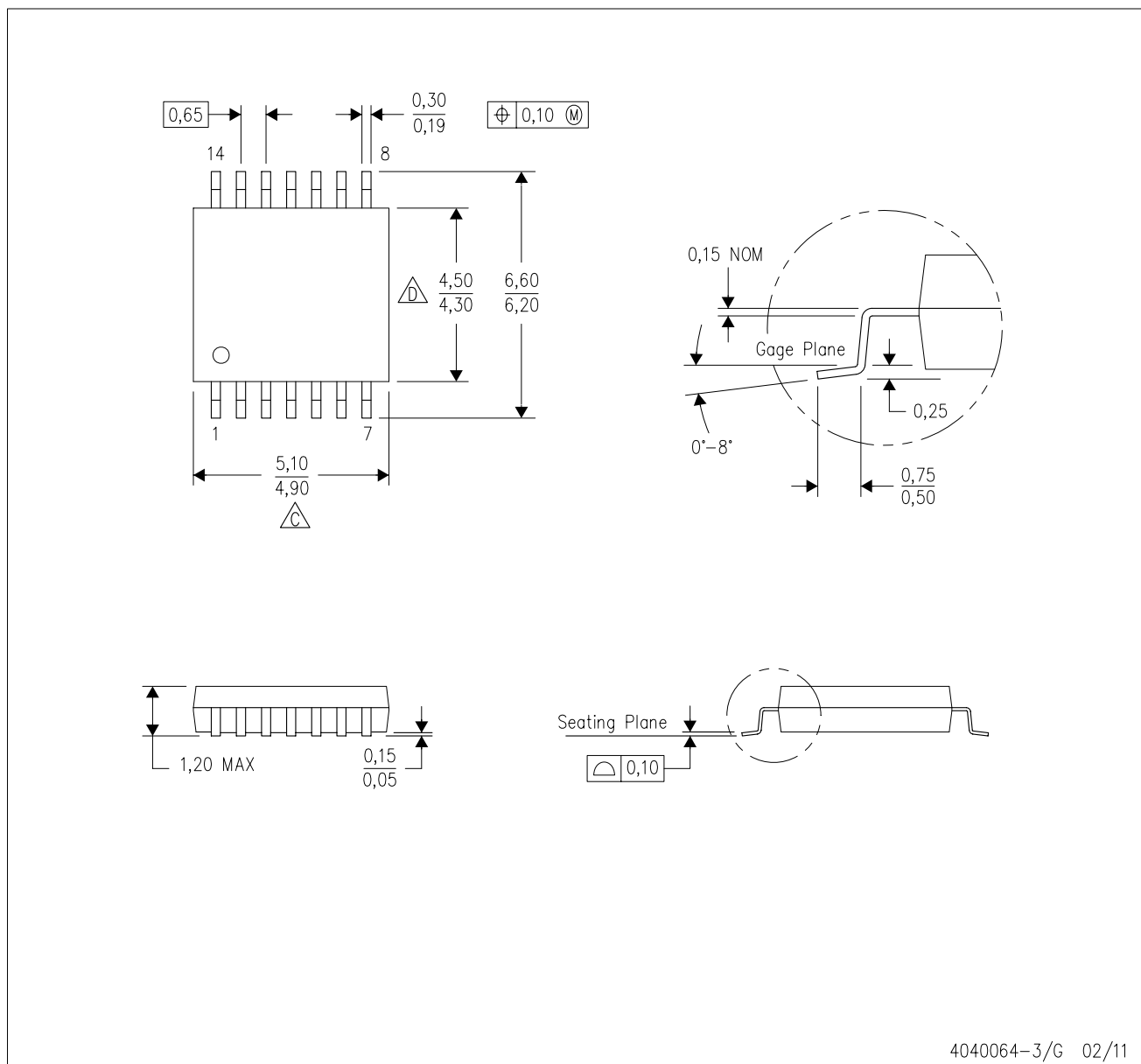
PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

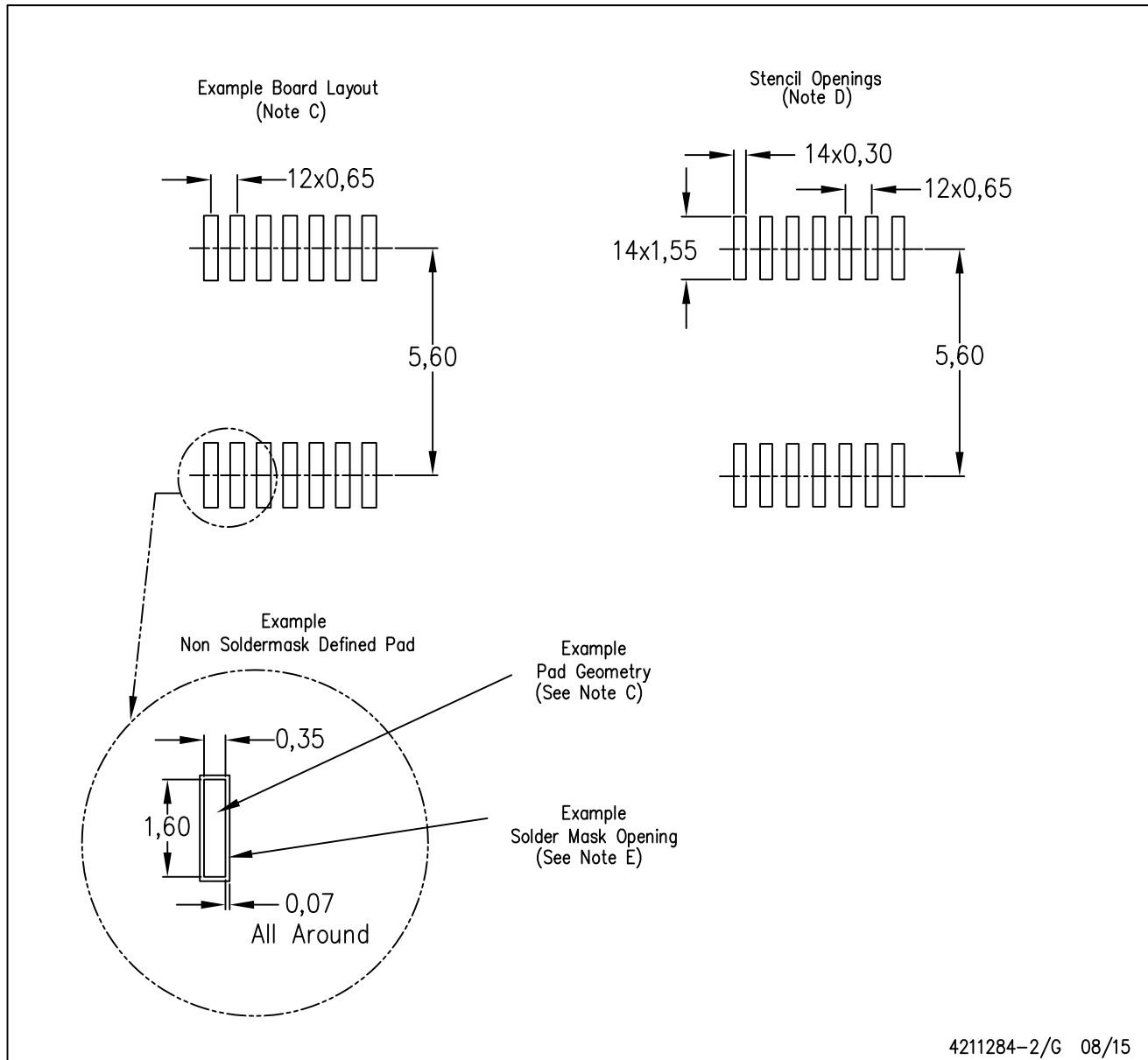
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

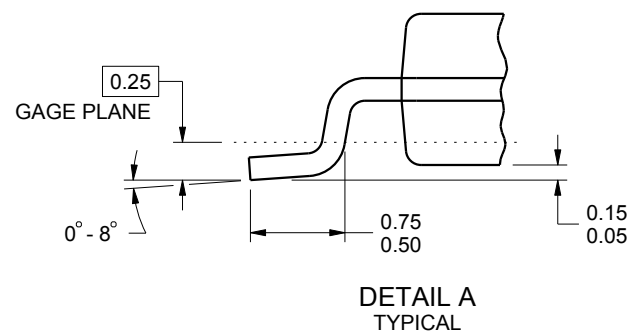
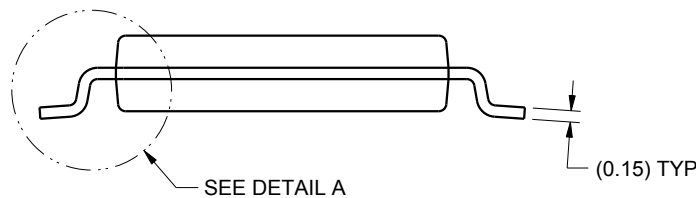
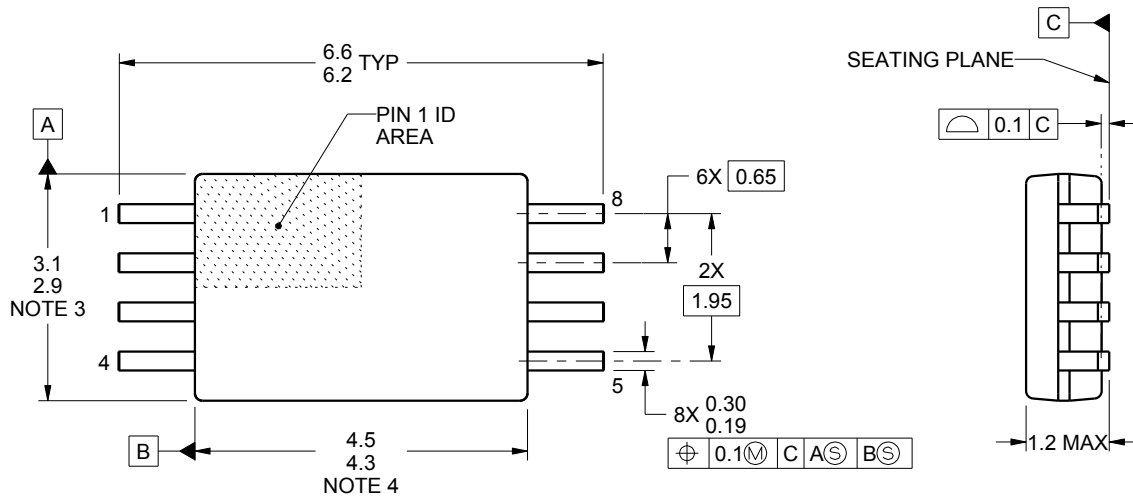
PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

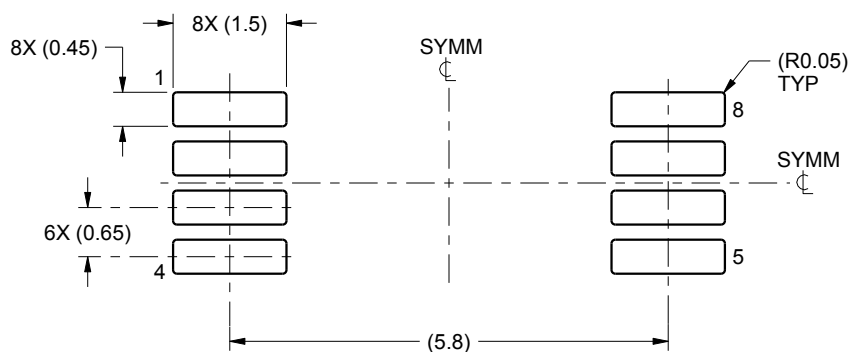
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

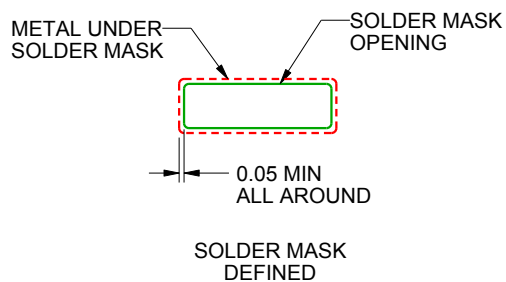
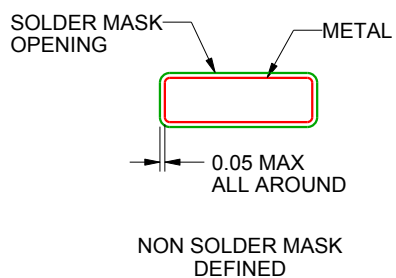
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

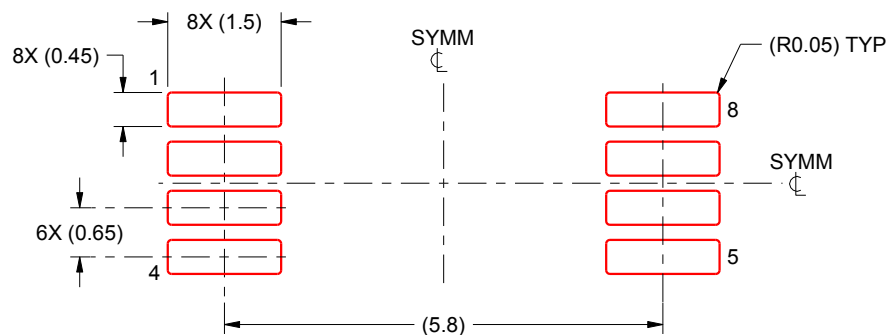
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

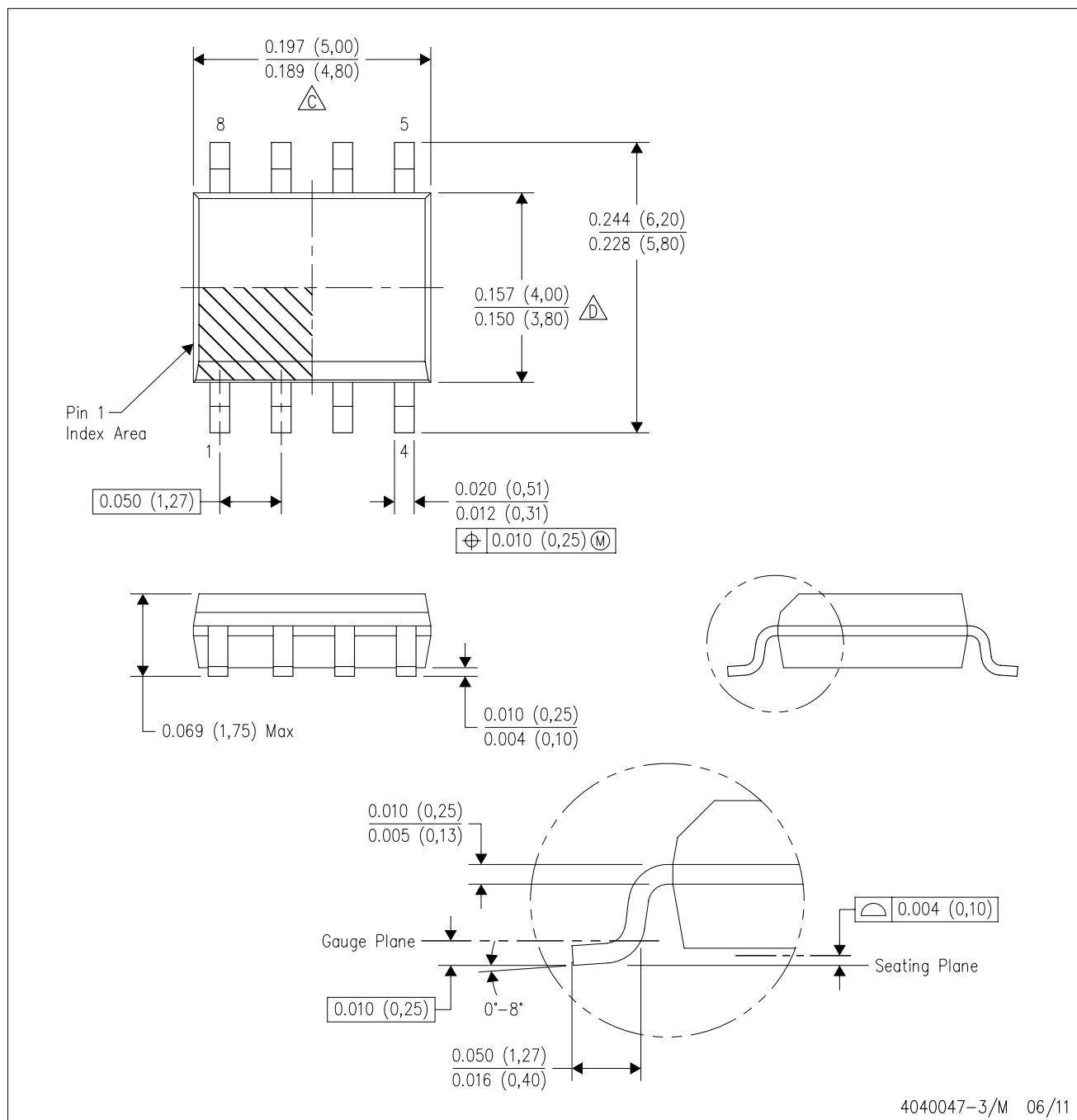
4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

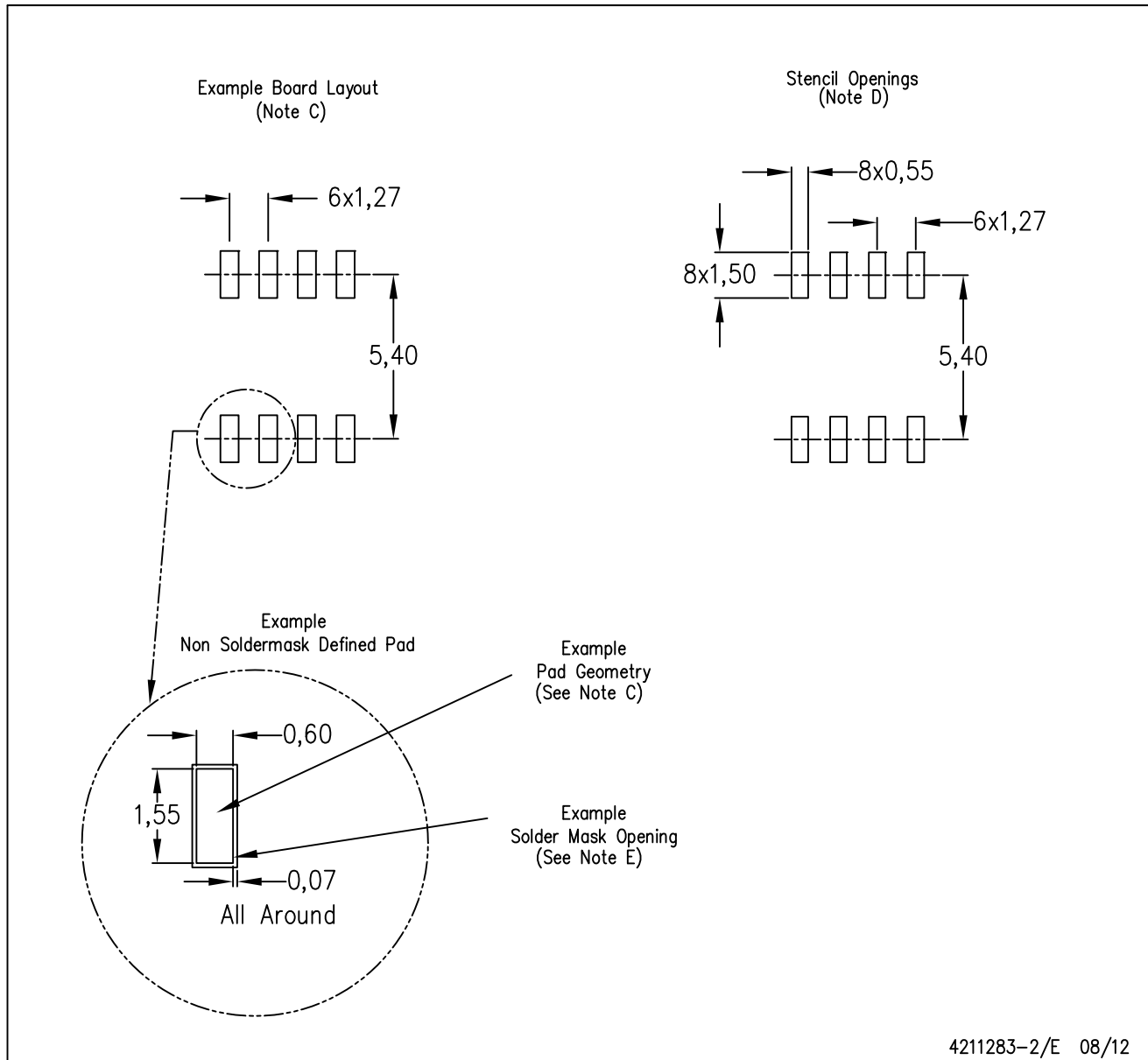


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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